

Keysight/ADS Workshop

Power Integrity Target Impedance Says it All, Power Delivery is AC not

Heidi Barnes, (Keysight Technologies)

SPEAKER

Heidi Barnes



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Heidi Barnes is currently the Power Integrity Product Owner for High-Speed Digital applications in the Design Engineering Software Group of Keysight Technologies. Her recent activities include the application of electromagnetic, transient, and channel simulators to solve signal and power integrity challenges. Author of over 20 papers on SI and PI, active member in developing the new IEEE P370 Standard involving interconnect S-parameter quality after fixture removal, and recipient of the DesignCon 2017 Engineer of the Year. Heidi graduated from the California Institute of Technology in 1986 with a bachelor's degree in electrical engineering.

Power Delivery for Digital Loads is AC not DC!

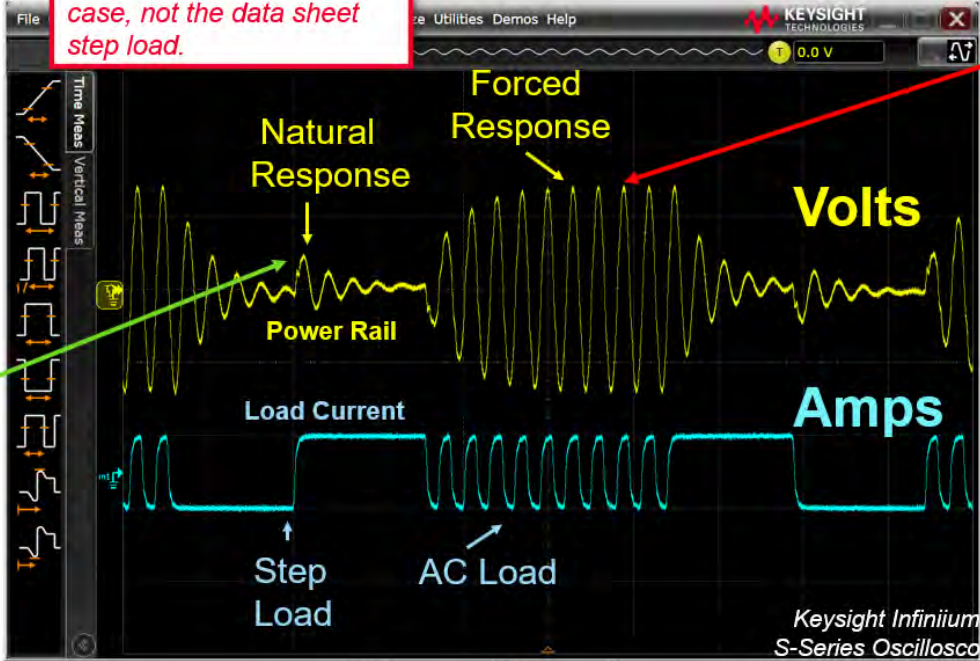
KEY TAKE AWAY
Forced response is worst case, not the data sheet step load.

New Method:
Finding the worst case Load

$$V = L \frac{di}{dt}$$

Old Method:
Step Load
Transient Test
(False Positive)

PASS
Datasheet
Design



FAIL
Over Voltage
Tx/Rx Bit Error
EMI
Crosstalk

Power Rail Noise Ripple is Not Intuitive

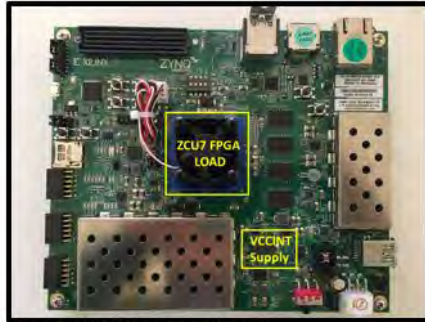
DesignCon 2020

A Method for Dynamic Load Current Testing with a Benchtop Power Supply

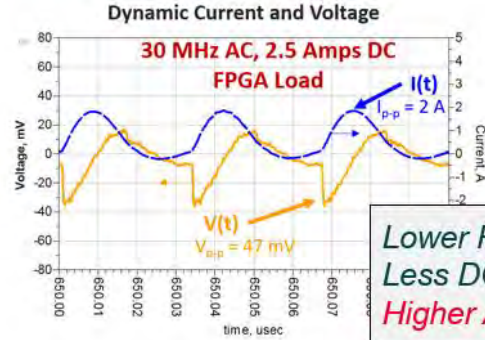
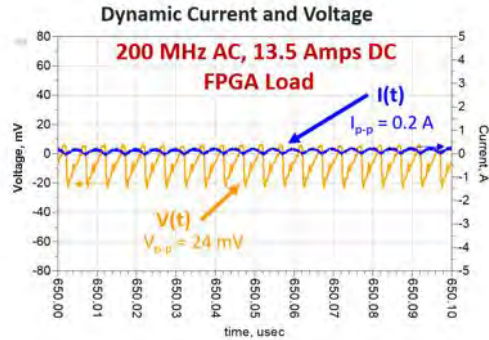
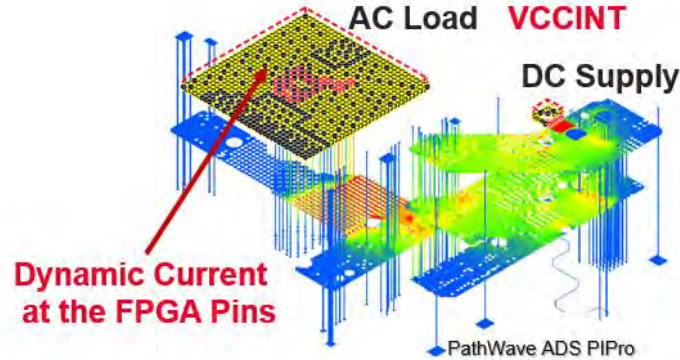
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Jack Carrel, Xilinx
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Steve Sandler, PICOTEST.com
steve@picotest.com



Xilinx ZCU104 Evaluation Kit



Lower Frequency
Less DC Current
Higher AC Noise!

Agenda

- ➔ • **Why Flat Impedance is the Design Goal**
 - Worst case PDN noise ripple is not intuitive
- **How to Measure Power Rail Impedances in the Micro-Ohms**
 - 2-Port Shunt Impedance where Z_{DUT} is a function of S_{21}
- **What is Wrong with Capacitor Vendor Data**
 - Vendor data for capacitor ESL typically includes mounting inductance which needs to be removed for connecting to EM simulations.

Power Integrity Starts with Target Impedance

Target Impedance Calculation

$$Z_{\text{Target}} = \frac{\Delta V_{\text{Max Ripple}}}{\Delta I_{\text{Max Transient Load}}}$$

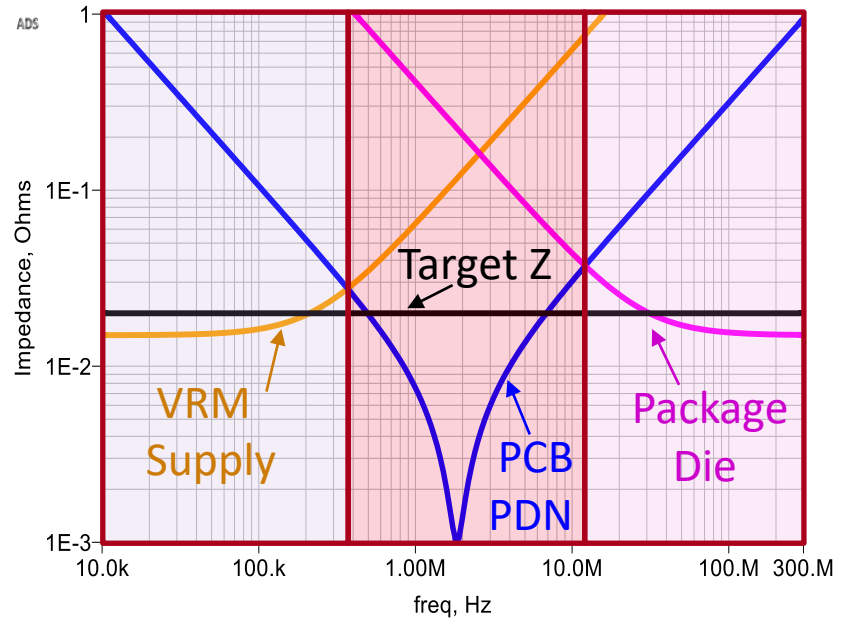
Using Impedance to Find Worst Case Power Rail Ripple

VRM = Low Pass Series R-L

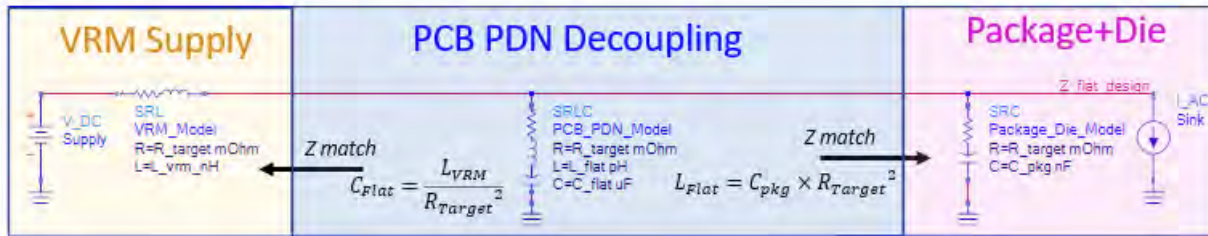
Capacitors = Band Pass Series C-R-L

Package/Die = High Pass R-C

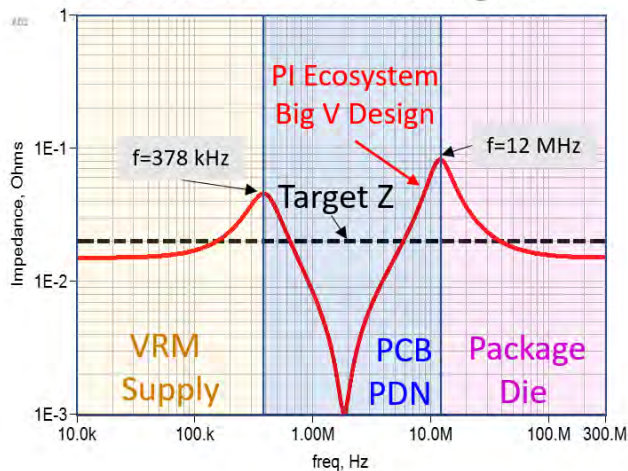
Individual Source Impedance
VRM, PCB PDN, and Package+Die



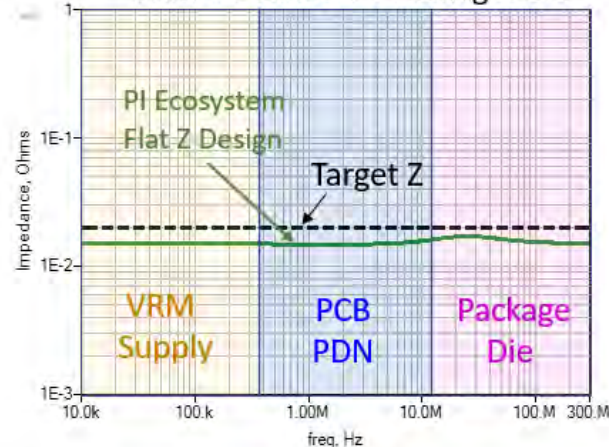
PI Ecosystem Simulation: VRM + PCB PDN + Load



PI Ecosystem Impedance
VRM + PCB PDN + Package+Die

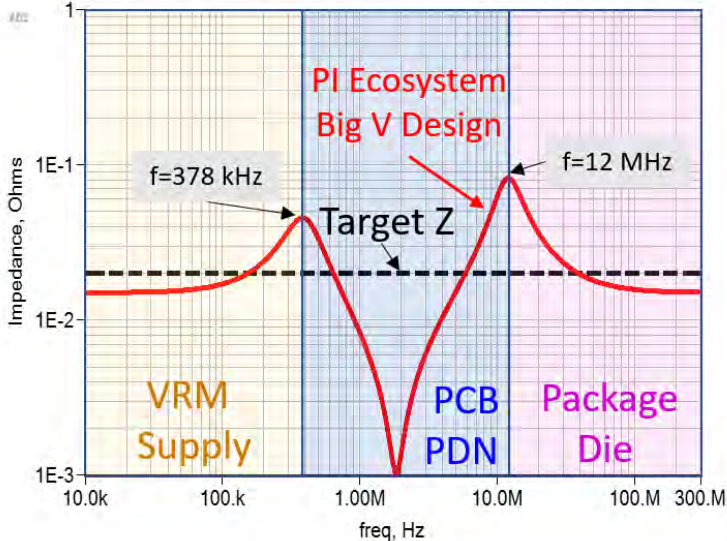


Flat Impedance Design
VRM + PCB PDN + Package+Die

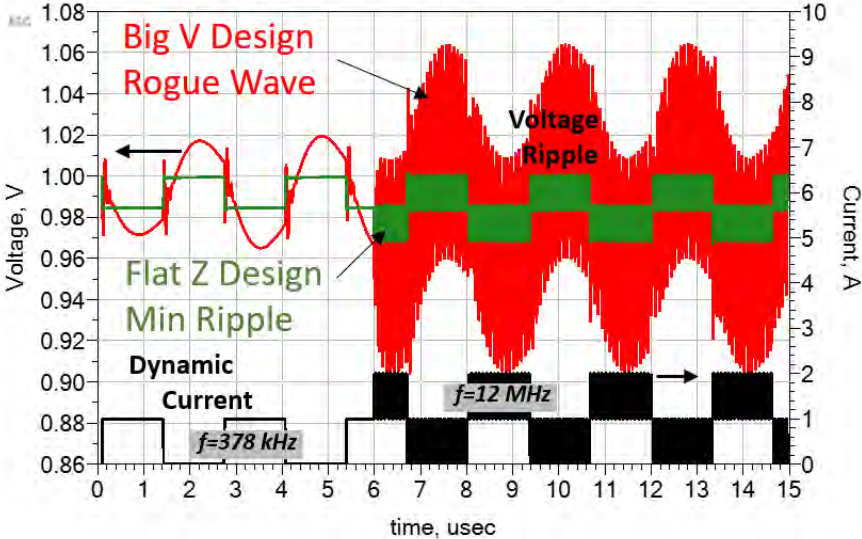


Worst Case Power Rail Noise Ripple

PI Ecosystem Impedance
VRM + PCB PDN + Package+Die



Dynamic Load at 378 kHz and 12 MHz
Big V PDN vs. Flat PDN



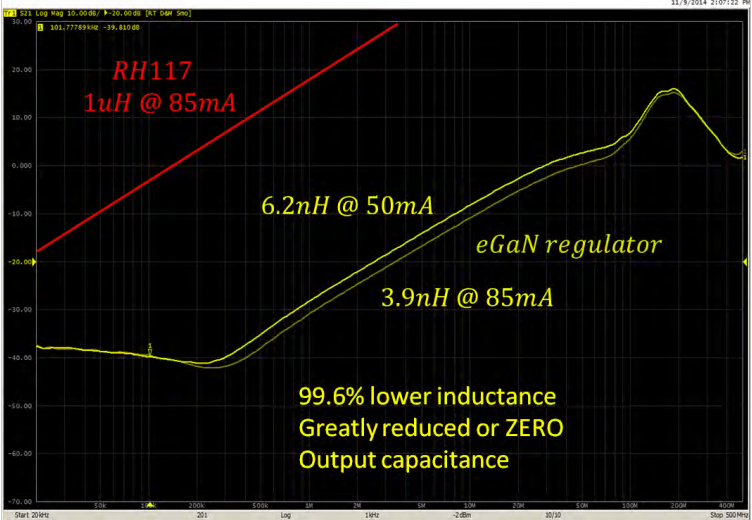
Why GaN is So Exciting for Power Delivery

....not just the size

$$C_{Flat} = \frac{L_{VRM}}{R_{Target}^2}$$

Maintaining a 0.1Ω maximum PDN impedance up to 2MHz requires 80uF for a RH117 and NO output cap for the eGaN regulator.

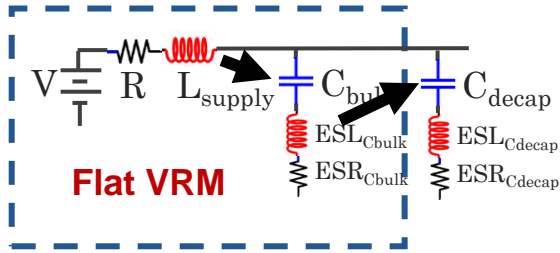
3.9nH is nearly equivalent to the ESL of a tantalum capacitor



Root Cause of Ringing on the Power Rail

Parallel inductance can resonate with the decoupling capacitance

Parallel L-C in the PDN



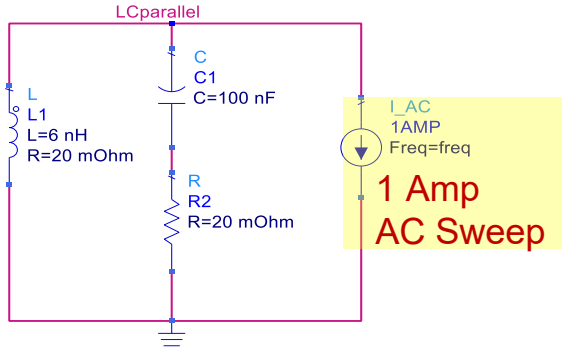
$$f_0 = \frac{1}{2\pi\sqrt{LC}}$$

$$\Delta V = \Delta I \cdot Z_{peak}$$

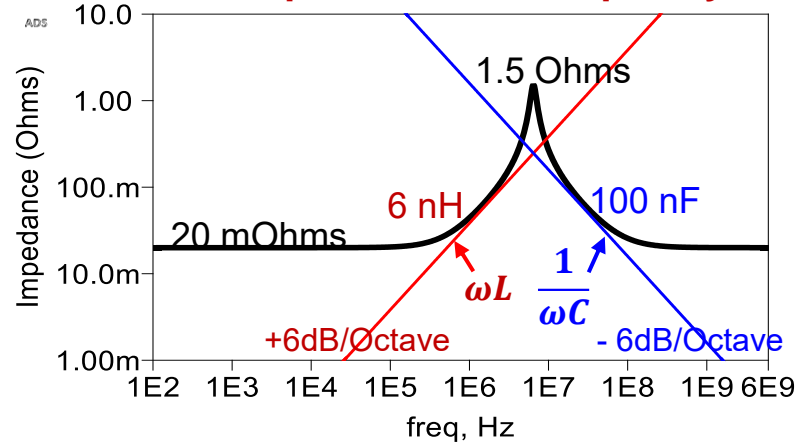
$$Z_{peak} = Z_0 \cdot Q$$

$$Z_0 = \sqrt{\frac{L}{C}}$$

$$Q = \frac{Z_0}{R_{total}}$$



Impedance vs. Frequency



$Z_{peak} = 1.5 \text{ Ohms}$

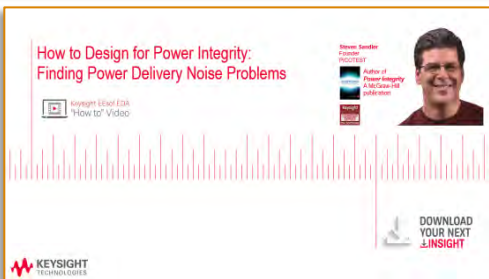
$Z_0 = 250 \text{ mOhms}$

Natural Step Response vs. Forced Response

A 2 Amp change yields 3 different responses

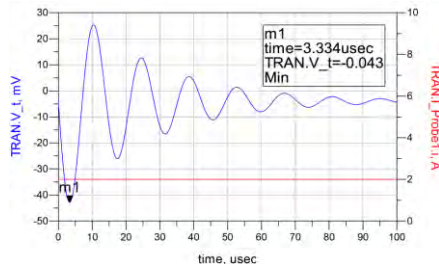
KEY TAKE AWAY

Watch the YouTube video
 “How to Design for Power Integrity: Finding Power Delivery Noise Problems”



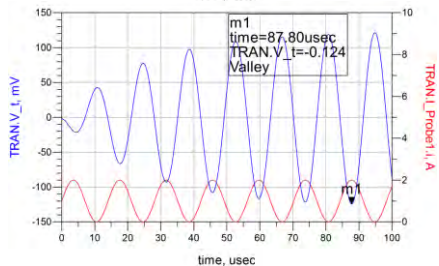
Step natural

$$\Delta V = \Delta I \cdot \sqrt{\frac{L}{C}} \cdot e^{-\frac{\pi}{4Q}} = 39mVpk$$



Sine forced

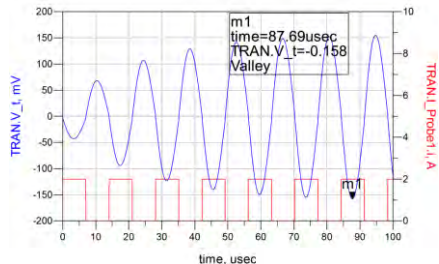
$$\Delta V = \Delta I \cdot \sqrt{\frac{L}{C}} \cdot \frac{Q}{2} = 123mVpk$$



*sine and square ΔV
 $\sim Q$ times the
 step response*

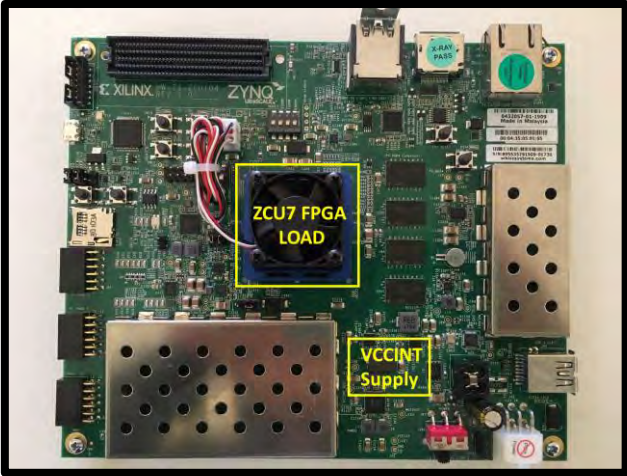
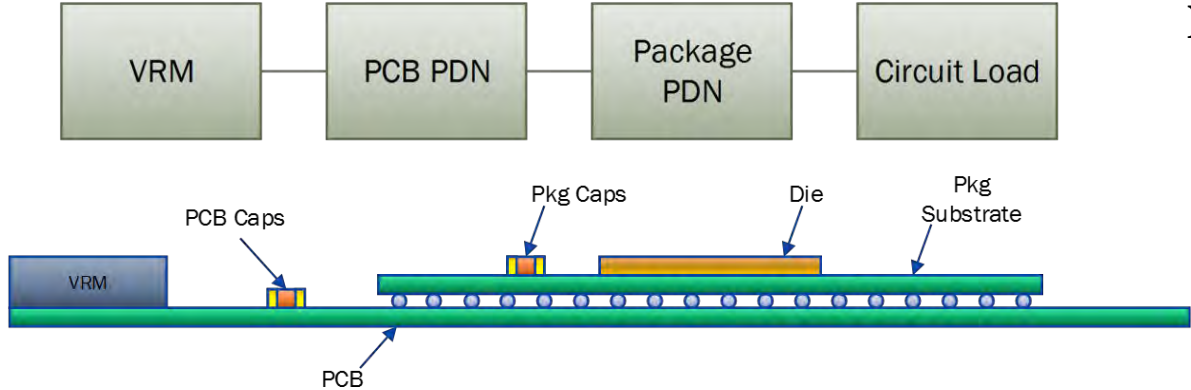
Square forced

$$\Delta V = \Delta I \cdot \sqrt{\frac{L}{C}} \cdot \frac{2Q}{\pi} = 157mVpk$$

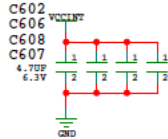
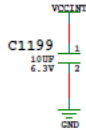
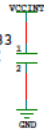
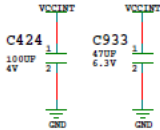
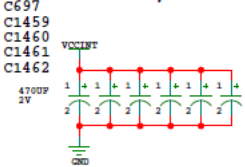


Why Lower ESR is Not Good, It Must be Matched

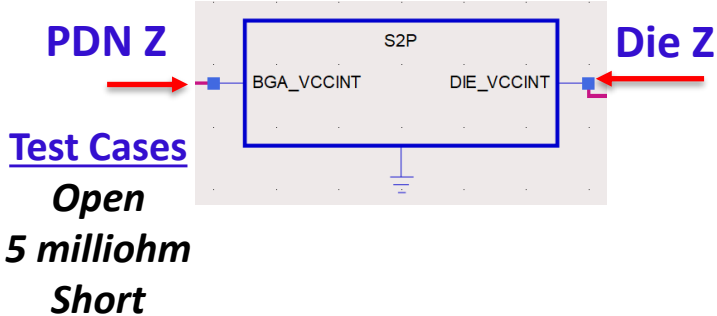
Xilinx Zynq UltraScale+ XCZU7EV-2FFVC1156 MPSoC



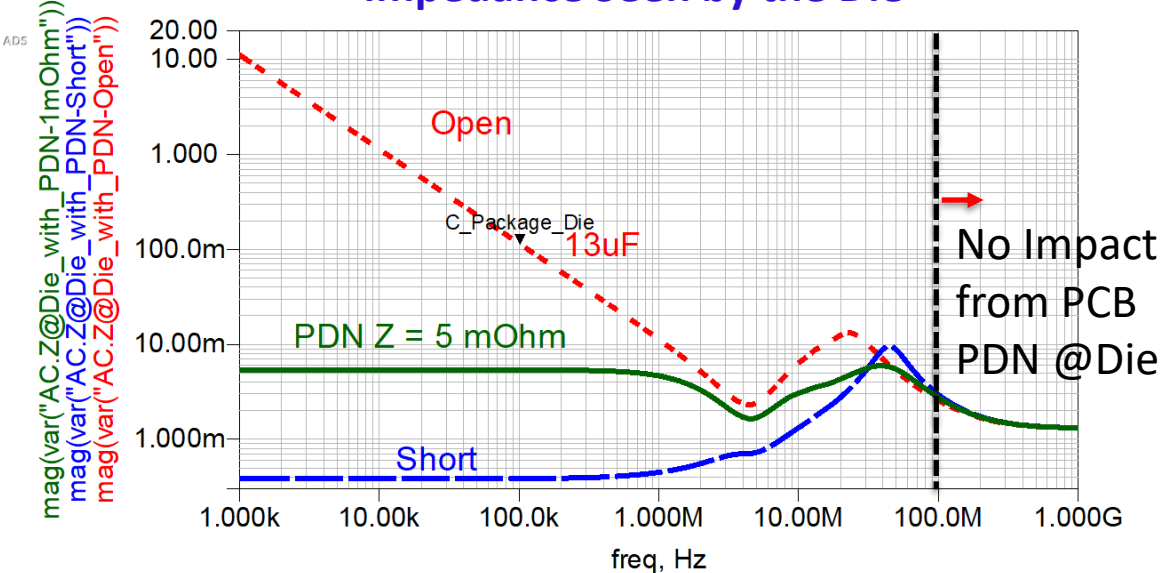
C696 VCCINT/VCCBRAM



FPGA Package/Die Model Connected to the PCB PDN

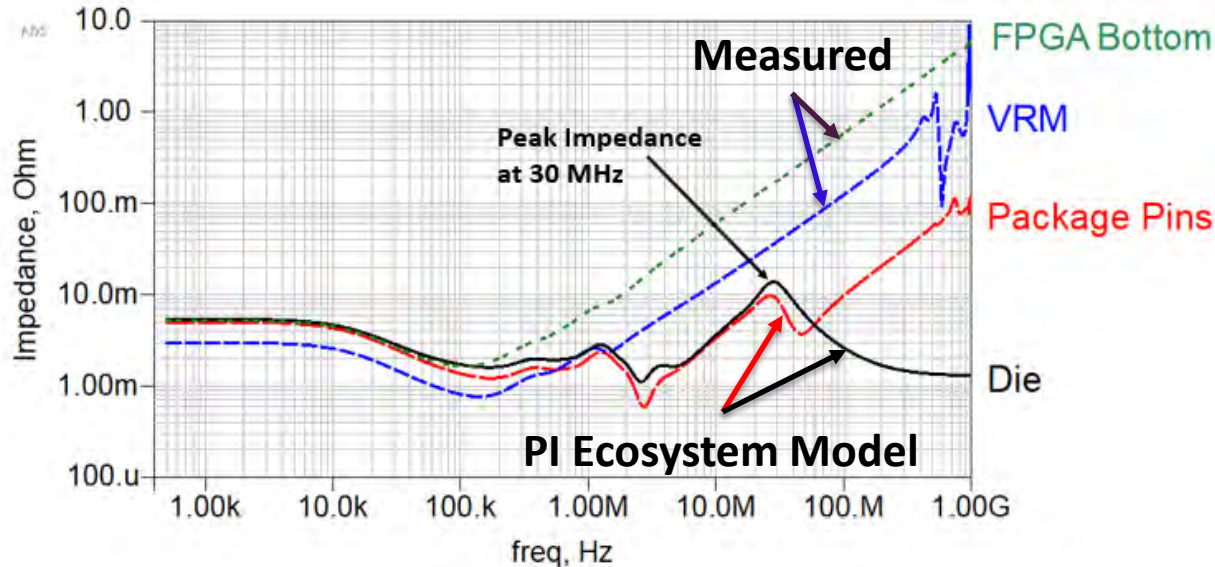


Impedance Seen by the Die



FPGA Package/Die, PCB PDN EM, and Capacitor Models are Critical

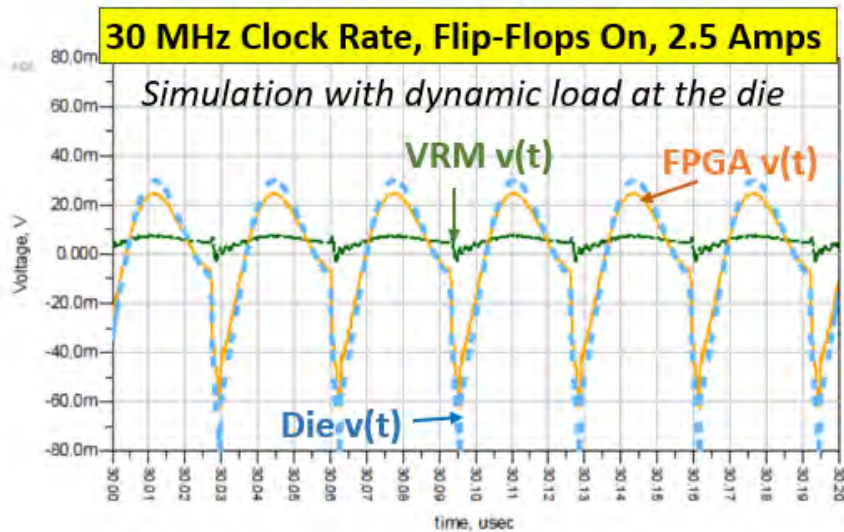
Impedance measurements did not see the resonance at 30 MHz!



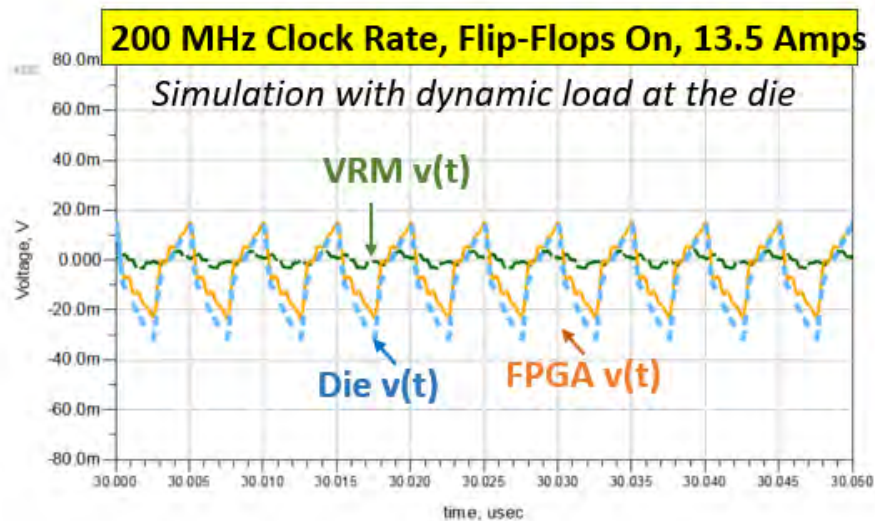
- Decoupling capacitors dominate the impedance of the VCCINT PDN.
- Measurements with VCCINT are only accessible on the bottom side of the FPGA and include the via inductance.
- PIPro PDN EM model with package/die (CPM) in ADS schematic accurately predicts impedance peak that measurement could not see.

Simulation Shows 30 MHz Toggling Has More Noise

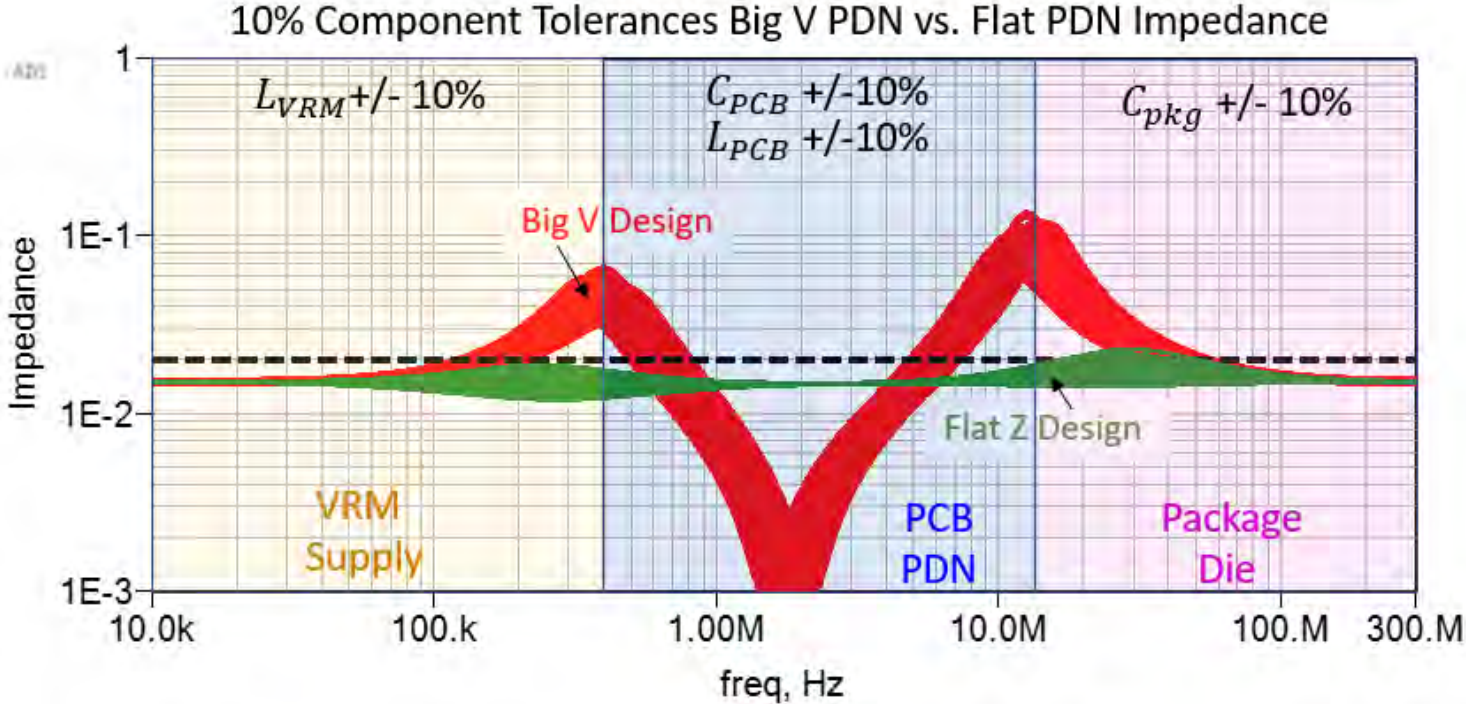
Lower frequency and lower current has higher noise



Higher frequency and higher current has less noise



Flat Impedance Design Provides Bigger Margins



Remember

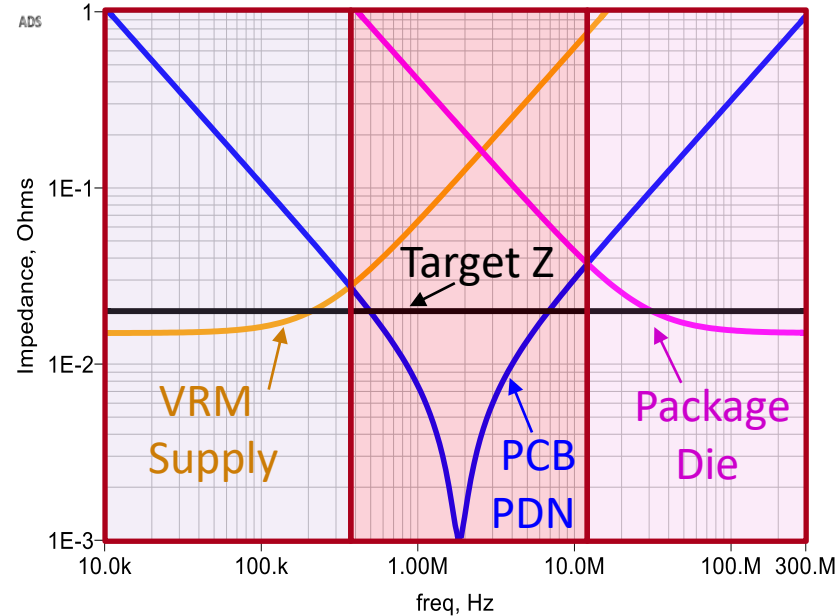
- Parallel L and C resonate in the time domain but are easier to find as impedance peaks in the frequency domain.
- Flat impedance minimizes the noise ripple by reducing the dynamic currents.
- Flat impedance is matched impedance with the simple rules of thumb based on

$$Z_0 = \sqrt{\frac{L}{C}}$$

$$C_{Flat} = \frac{L_{VRM}}{R_{Target}^2}$$

$$L_{PCB} = C_{Pkg} * R_{Target}^2$$

Individual Source Impedance
VRM, PCB PDN, and Package+Die



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- Worst case PDN noise ripple is not intuitive



- **How to Measure Power Rail Impedances in the Micro-Ohms**

- 2-Port Shunt Impedance where Z_{DUT} is a function of S_{21}

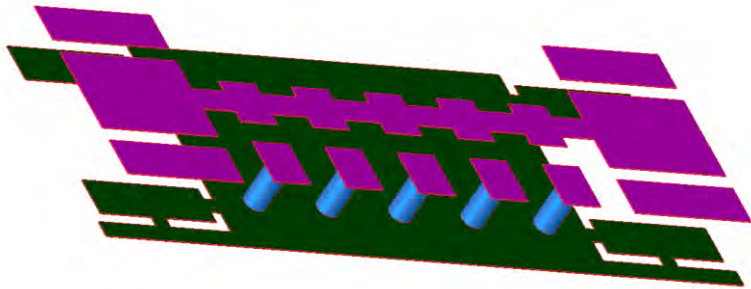
- **What is Wrong with Capacitor Vendor Data**

- Vendor data for capacitor ESL typically includes mounting inductance which needs to be removed for connecting to EM simulations.

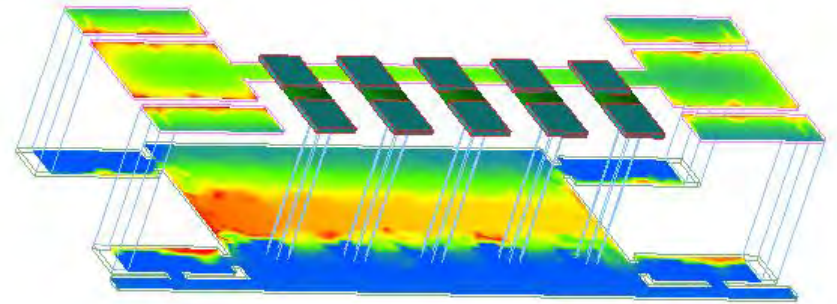
Parallel Capacitors Increase C and Decrease L and R



Layout



EM Simulation with PIPro

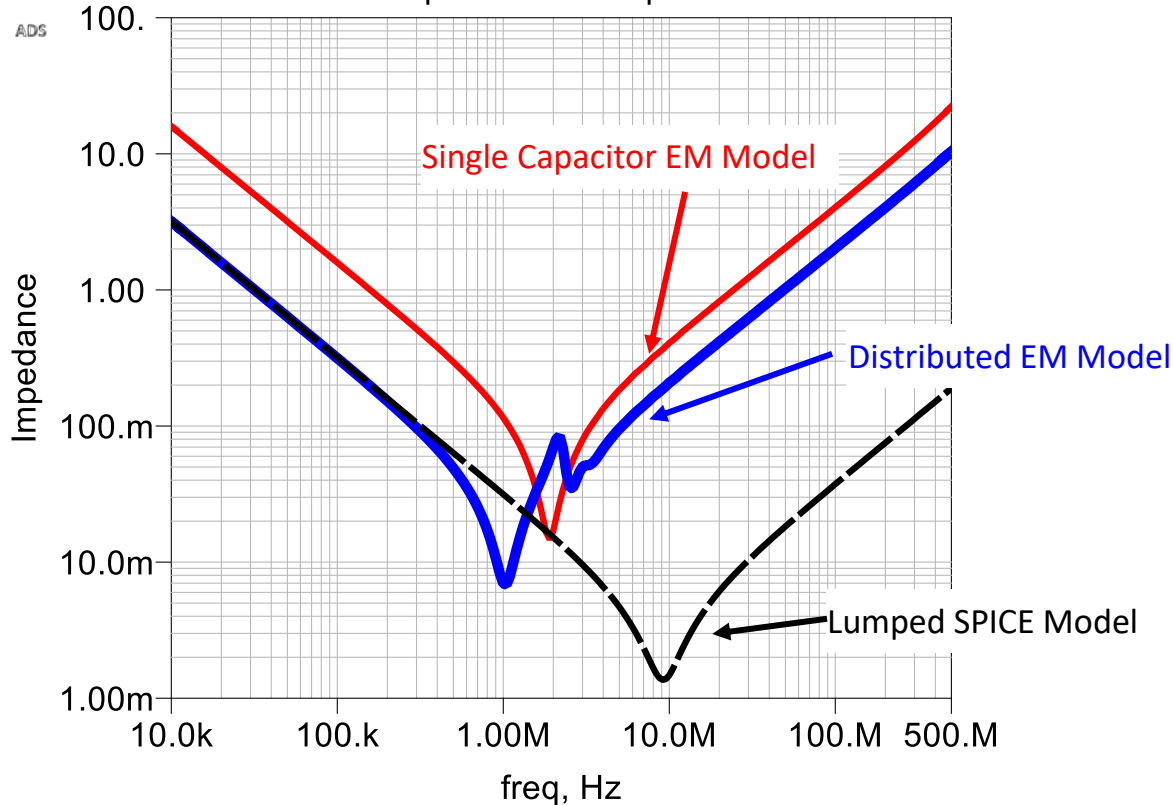


EM Models Capture Real World Parasitics – Parallel Caps

1 Capacitor vs. 5 Capacitors

Paralleling same value caps

	C	ESR	ESL
C1	1 uF	7 mΩ	300 pH

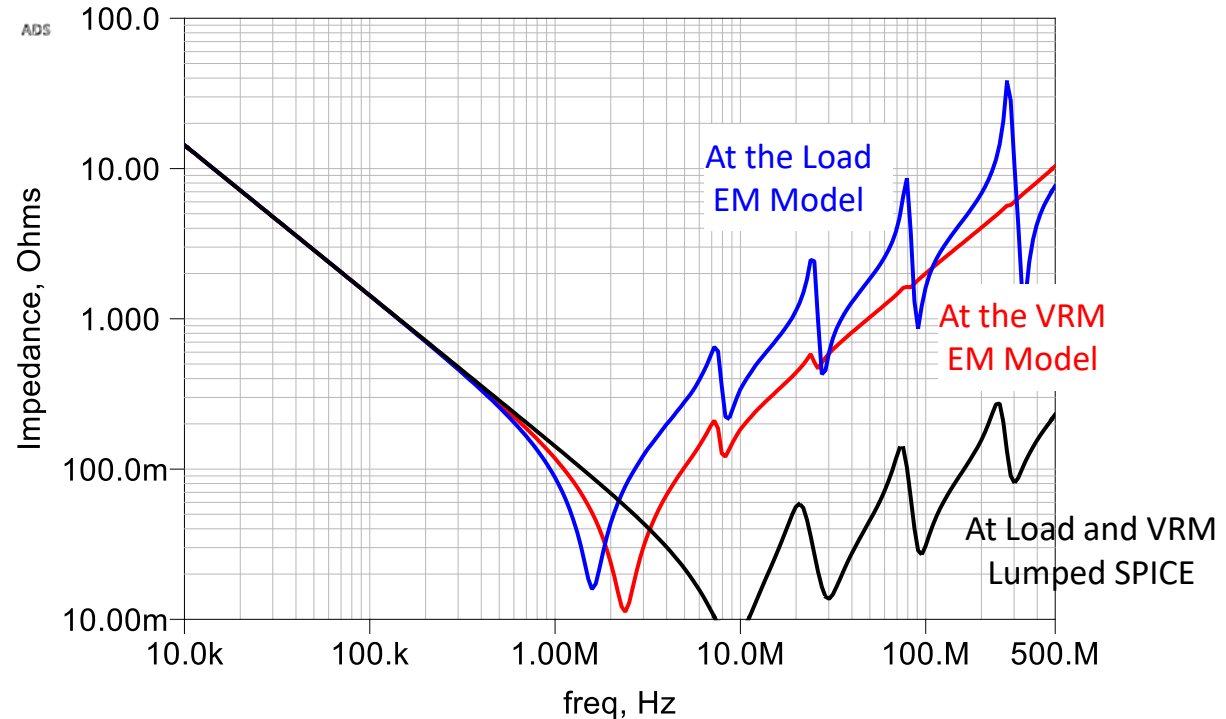
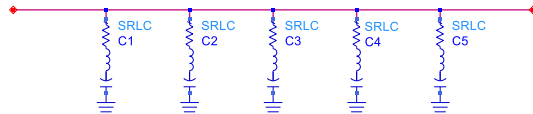


EM Models Capture Real World PCB Parasitics $Z_{vrm} \neq Z_{load}$

Z at Load vs. Z at VRM

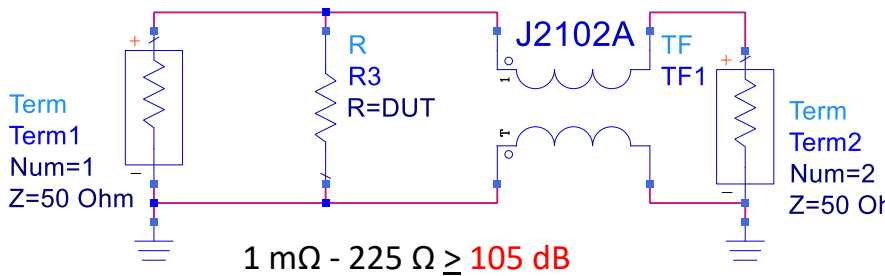
Capacitor Loading by the Decade

	C	ESR	ESL
C1	1 uF	7 mΩ	300 pH
C2	0.10uF	15 mΩ	300 pH
C3	0.01uF	30 mΩ	300 pH
C4	0.001uF	100 mΩ	300 pH
C5	100pF	200 mΩ	300 pH

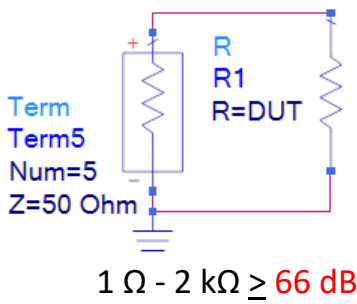


2-Port Shunt Impedance

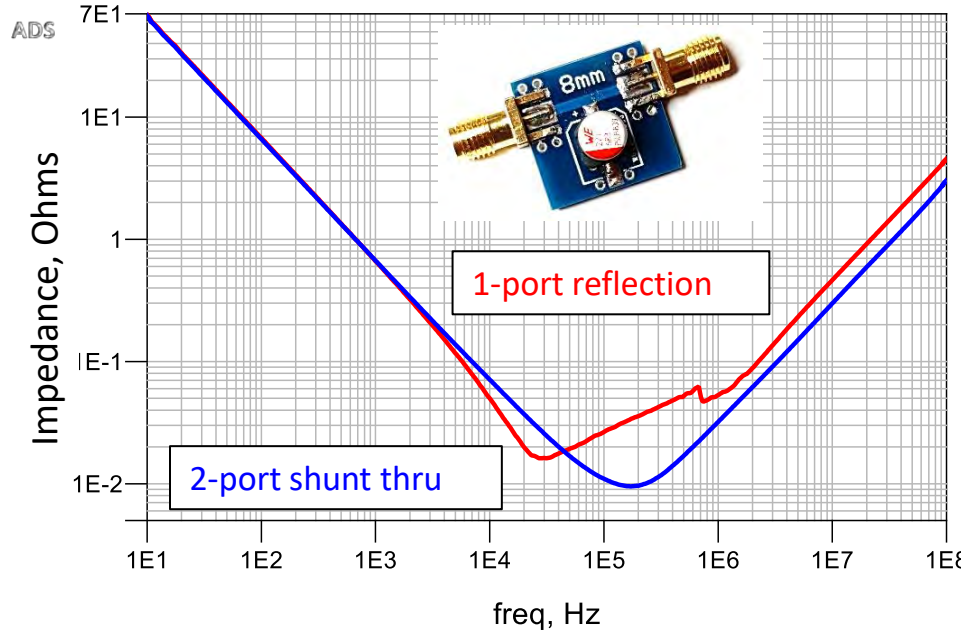
2-Port Shunt



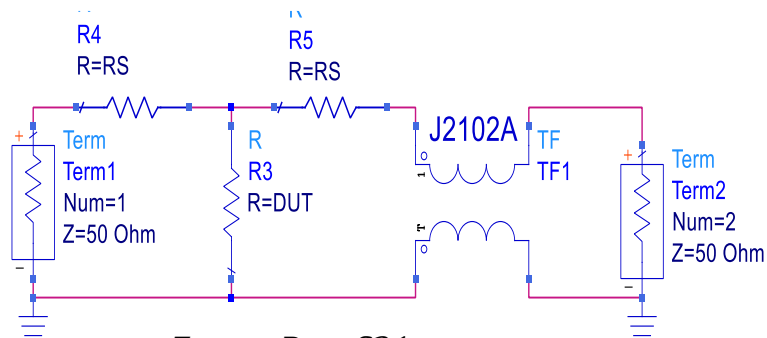
1-Port



220uF Aluminum Polymer



Increase Port Impedance Shift the Measurement Range



$$Z_{DUT} = \frac{Z_{ref} + R_s}{2} \frac{S21}{1 - S21}$$

$$S21 = \frac{2 \cdot Z_{DUT}}{2 \cdot Z_{DUT} + Z_{ref} + R_s}$$

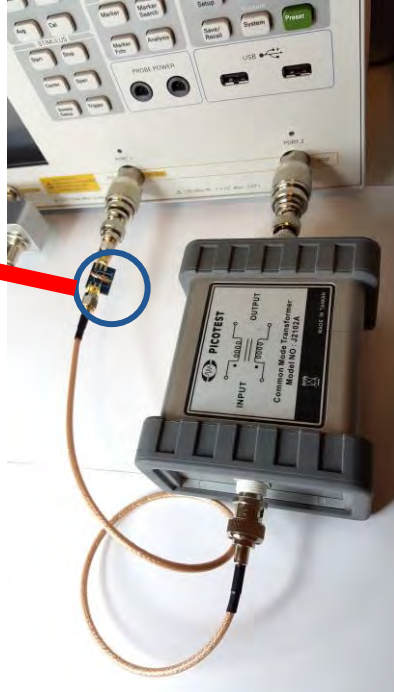
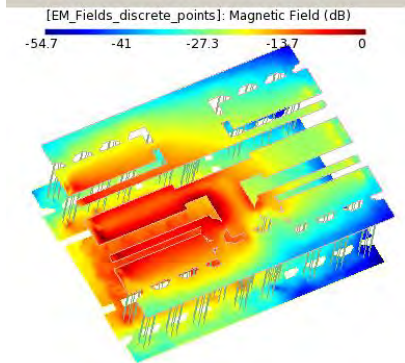
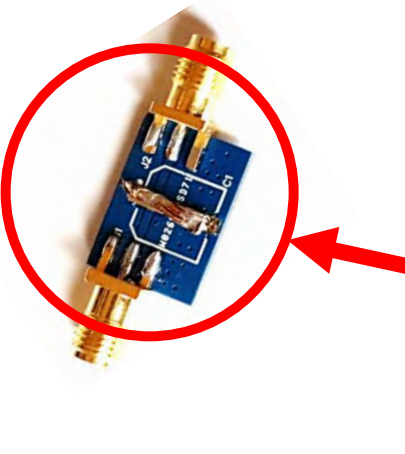
Series Resistor	Min Z	Max Z
200Ω	5 mΩ	1.125kΩ
450Ω	10 mΩ	2.25kΩ
499Ω	11mΩ	2.48kΩ
950Ω	20 mΩ	4.5kΩ



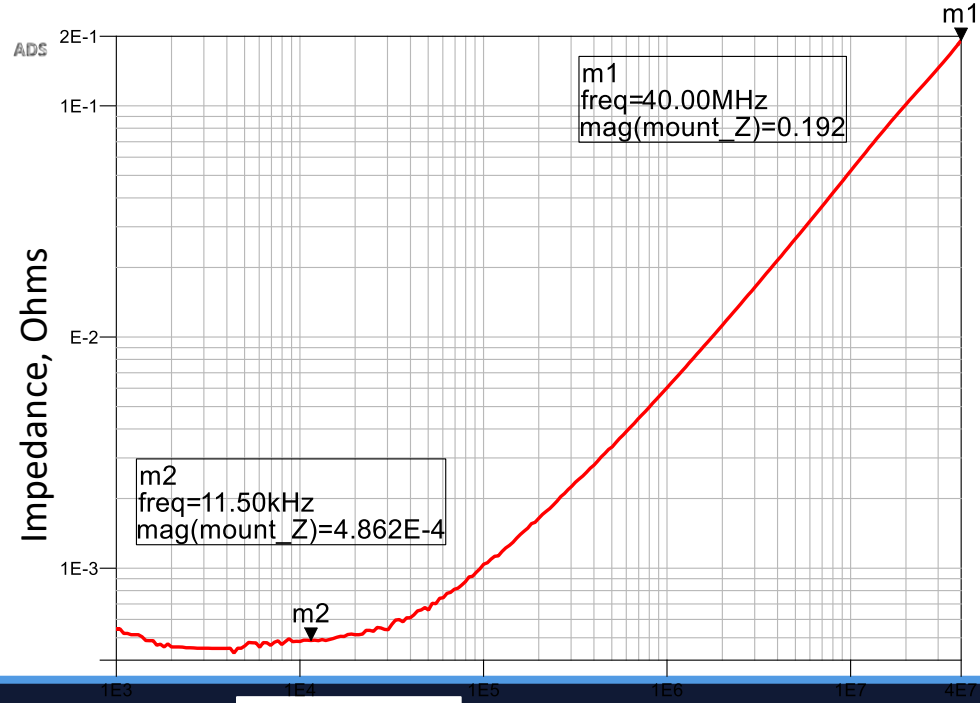
Measurement Range



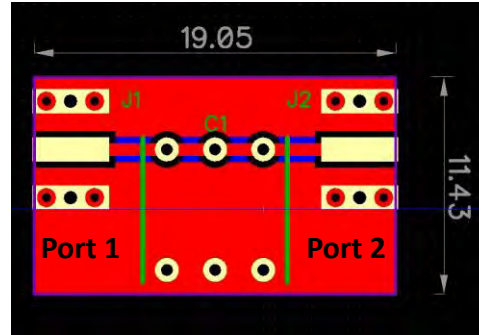
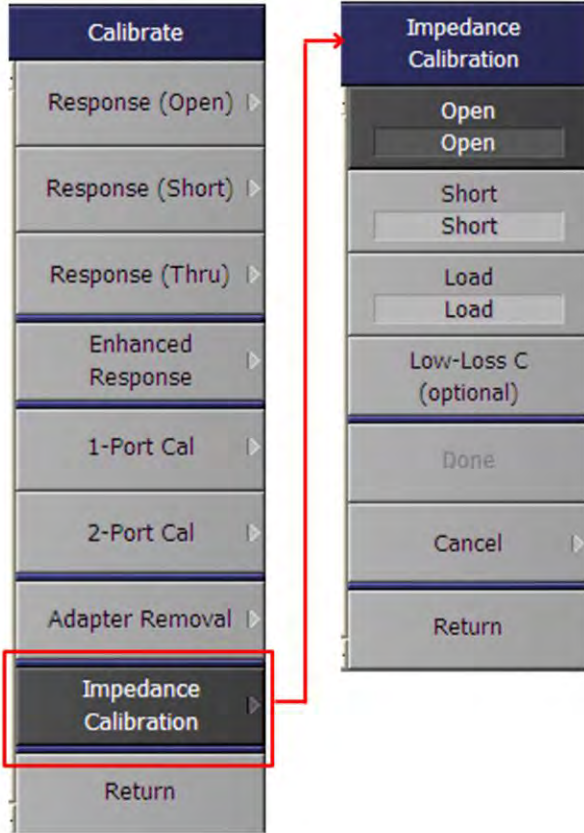
Mounting Inductance Measured with Short to Ground



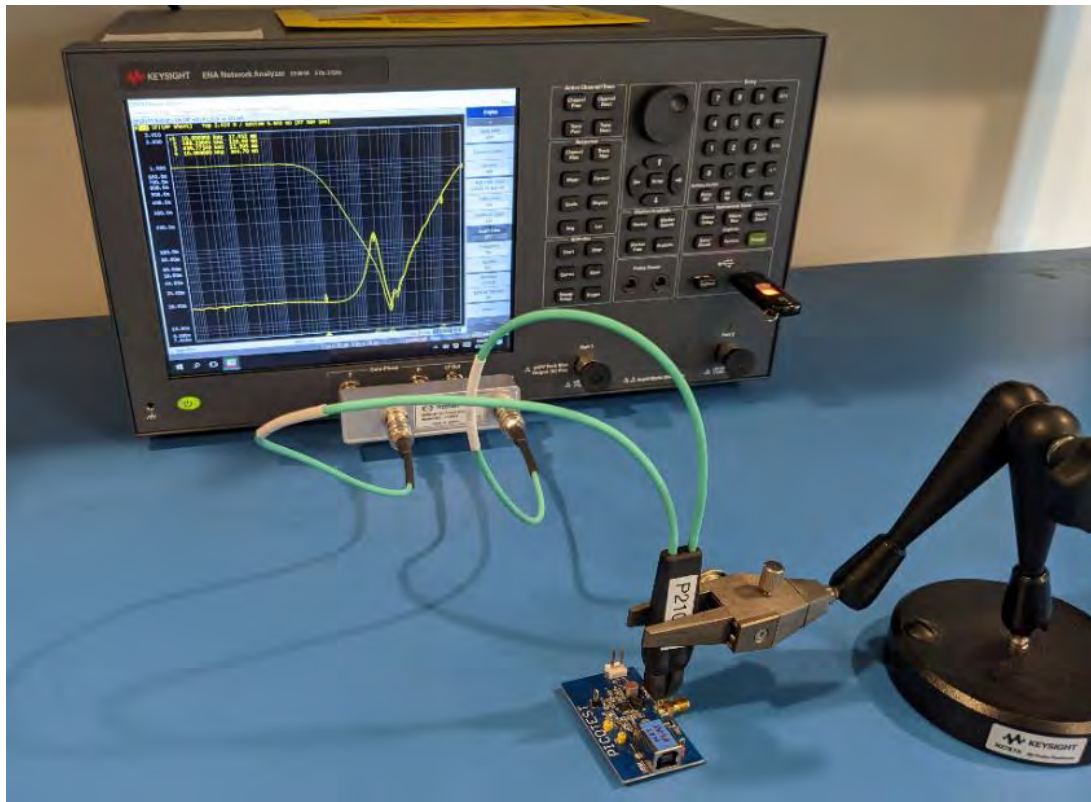
$$L_{mount} = \frac{0.192}{2\pi \cdot 40MHz} = 764pH$$



2-Port Shunt Impedance Setup Example



2-Port Shunt Impedance Browser Probe



Keysight E5061B
and the Picotest
P2102 Probe



SOL Calibration

*Courtesy of
Benjamin Danna
and Steve Sandler*

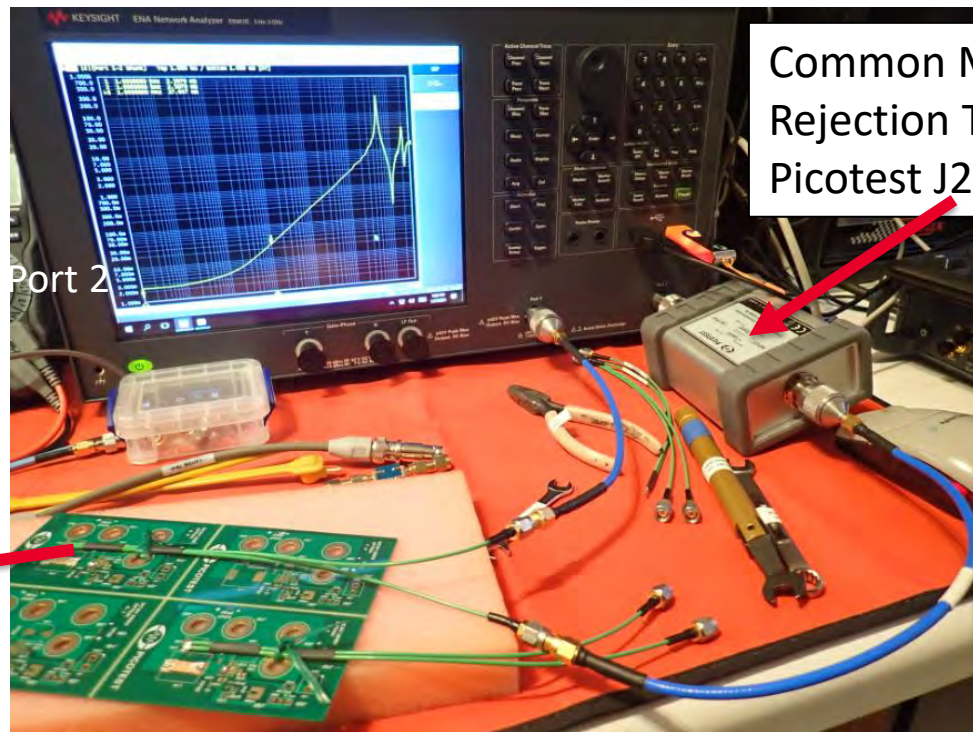


Avoiding Ground Loops between Port 1 and Port 2

High Frequency 5Hz to 3GHz S-parameter Ports

Simple response thru calibration with the two soldered together cables before attaching to the DUT.

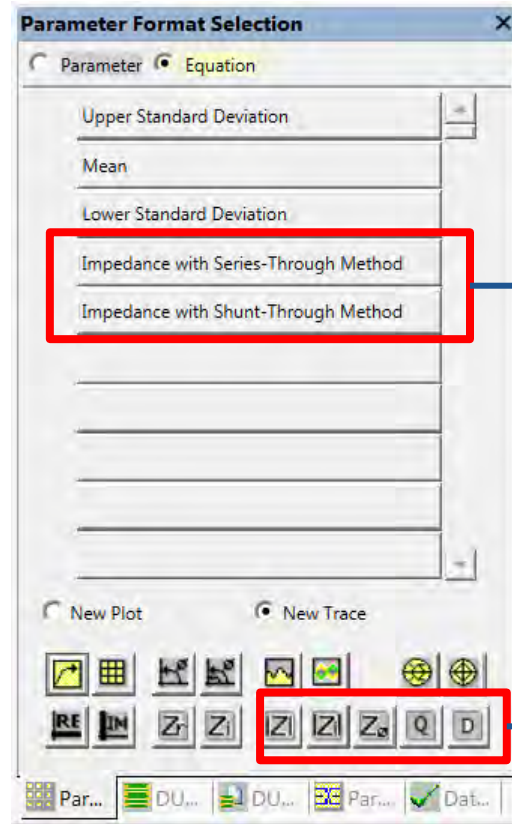
Two 50 Ohm Coax Cables Soldered together at the DUT



Common Mode Rejection Transformer Picotest J2102B

Port 2

VNA Tool Options for 2-Port Shunt Z: PLTS Can Help



Python Equations:

- a. For the Series-through method of measuring a power plane

$$Z_{DUT} = (50 \times 2) \times ((1 - S_{21}) / S_{21})$$

- b. For the Shunt-through method of measuring a power plane

$$Z_{DUT} = 50 \times S_{21} / (2 \times (1 - S_{21}))$$

Five Power Integrity formats:

|Z|: impedance magnitude

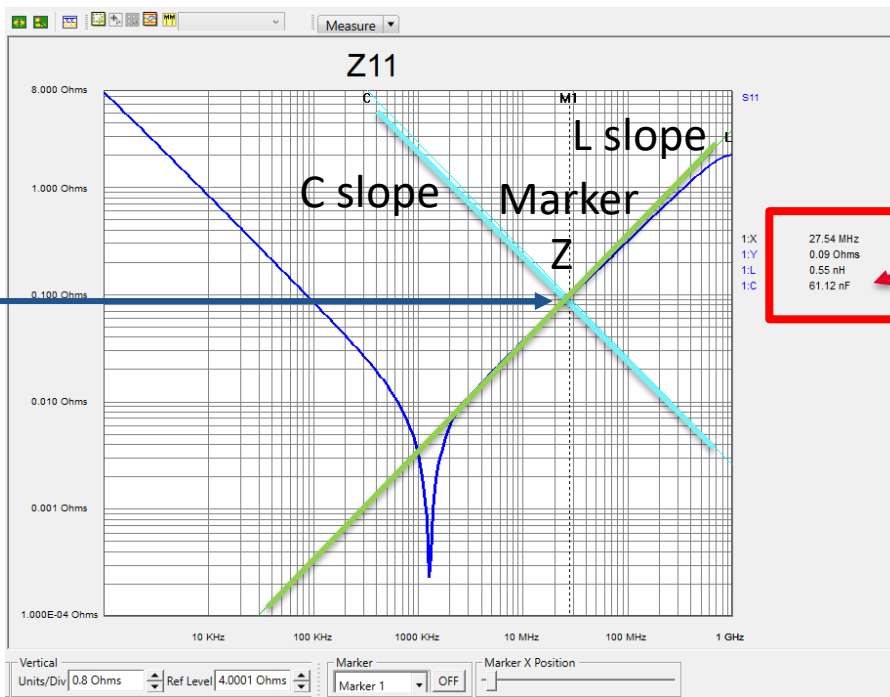
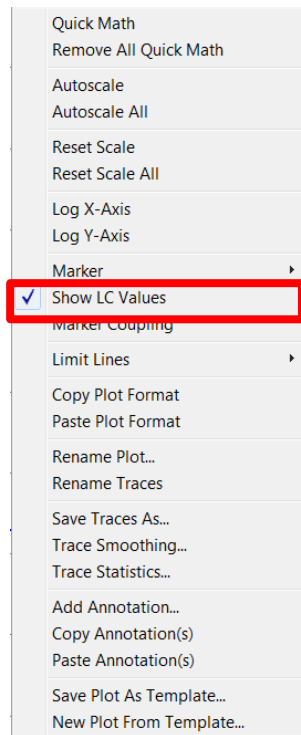
|Zi|: impedance imaginary magnitude

Z_{ϕ} : impedance angle

Q : quality factor

D : dissipation factor

Show LC Values for Power Integrity Measurements



- Line up the C-slope to measure C
- Line up the L slope to measure L

61nF

The button “Show LC Values” locates in right click menu.

The button only works for the new five impedance formats.

When it is selected, the LC value will be shown in marker.

Remember


- Parallel L and C resonate in the time domain but are easier to find as impedance peaks in the frequency domain.
- Flat impedance minimizes the noise ripple by reducing the dynamic currents.
- Flat impedance is matched impedance with the simple rules of thumb based on

$$Z_0 = \sqrt{\frac{L}{C}}$$

$$C_{Flat} = \frac{L_{VRM}}{R_{Target}^2}$$

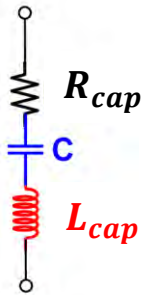
$$L_{PCB} = C_{Pkg} * R_{Target}^2$$

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Capacitors Have Series L and Series R

Capacitor Model



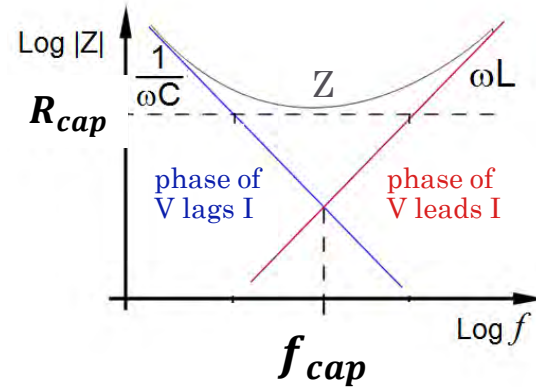
Impedance Equation

$$Z = R_{cap} + \left(j\omega L_{cap} - j\frac{1}{\omega C} \right)$$

$$f_{cap} = \frac{1}{2\pi\sqrt{L_{cap} \times C}}$$

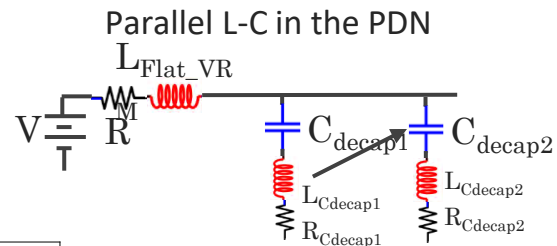
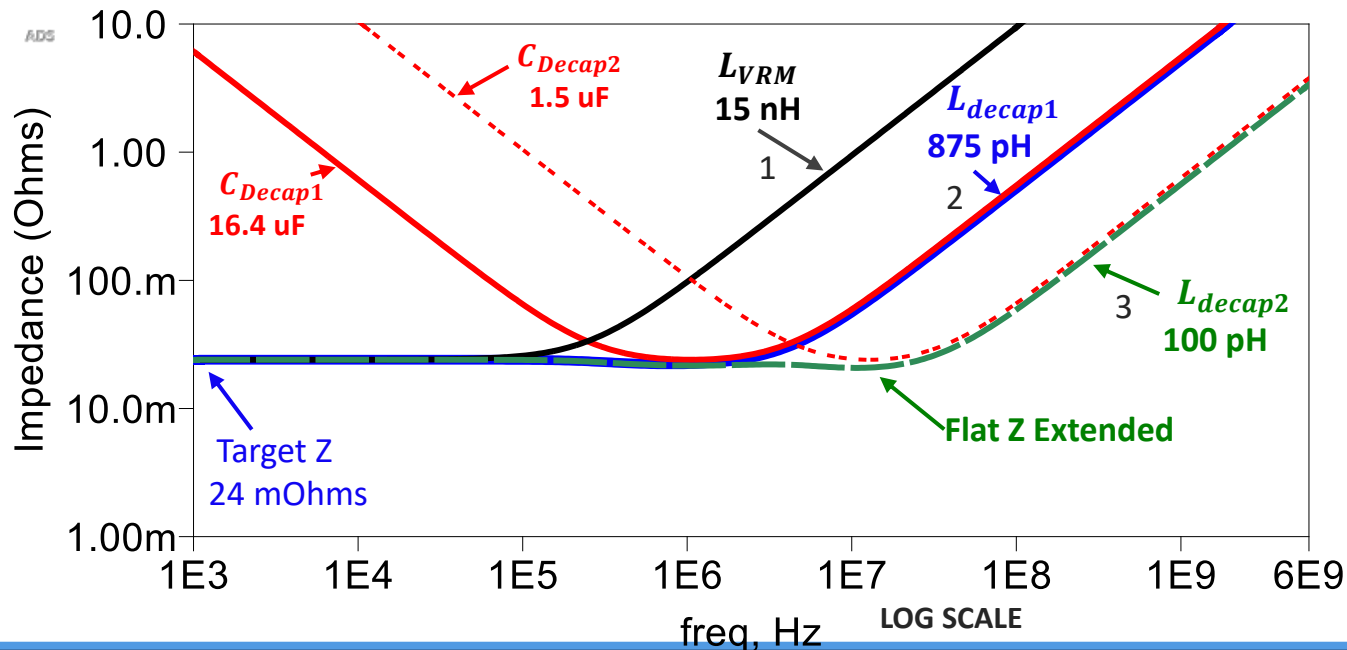
Voltage and current are in phase at f_{cap}

Series RLC Impedance vs. Frequency



Adding Decoupling Capacitors to Reduce L

Frequency Domain
Power Supply Output Impedance

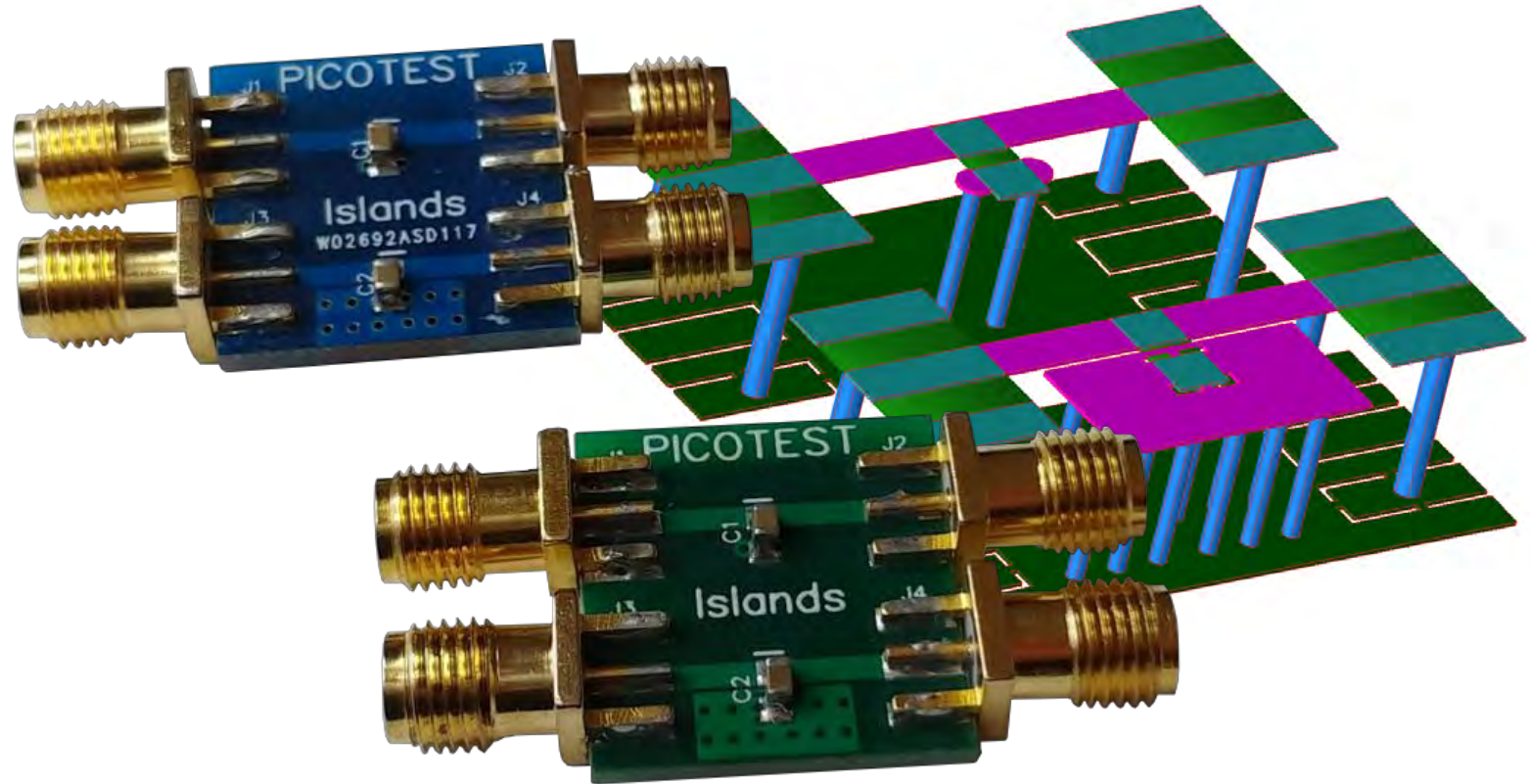


$$C_{decap2} = \frac{L_{decap1}}{Z_{Target}^2}$$

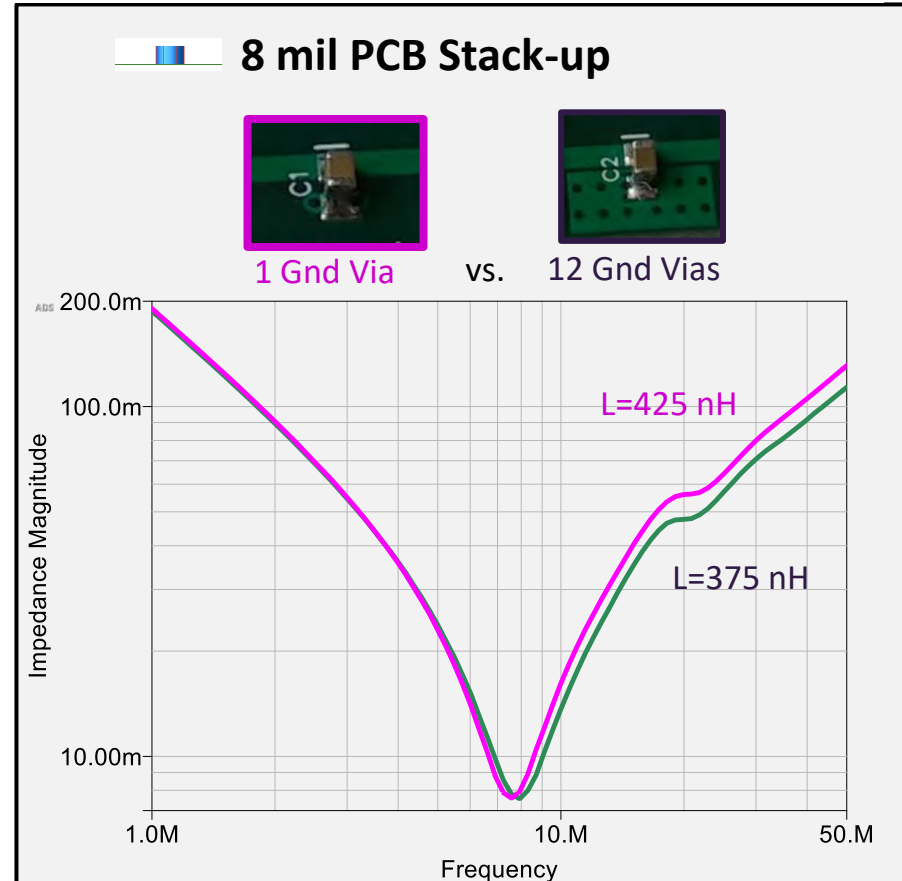
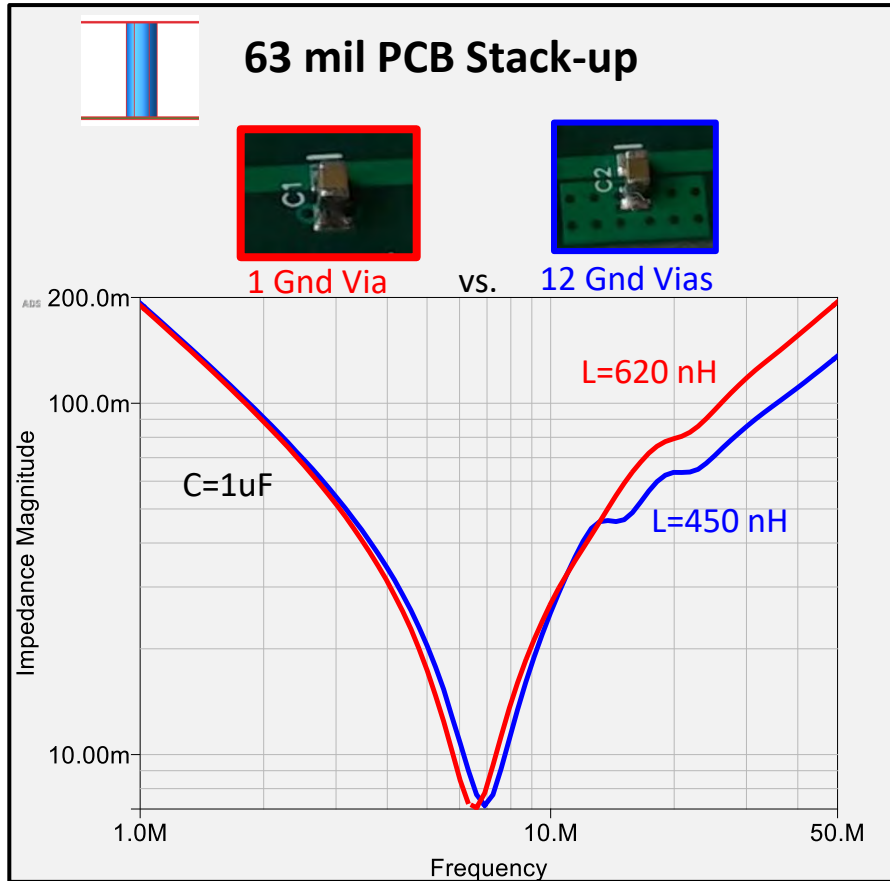
$$= \frac{875\text{pH}}{(24\text{ mOhm})^2}$$

$$\approx 1.5\text{ uF}$$

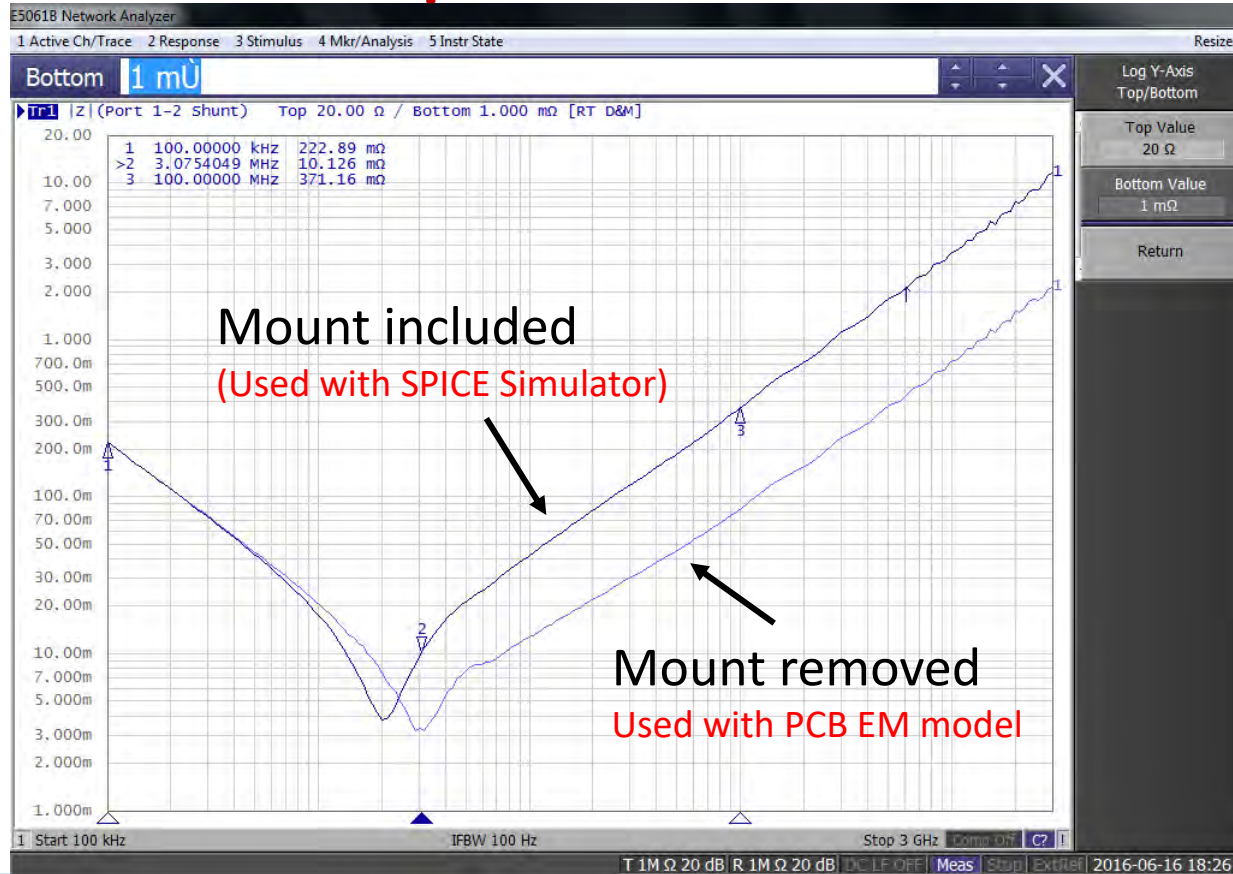
Surface Mount Capacitors with the Lowest L



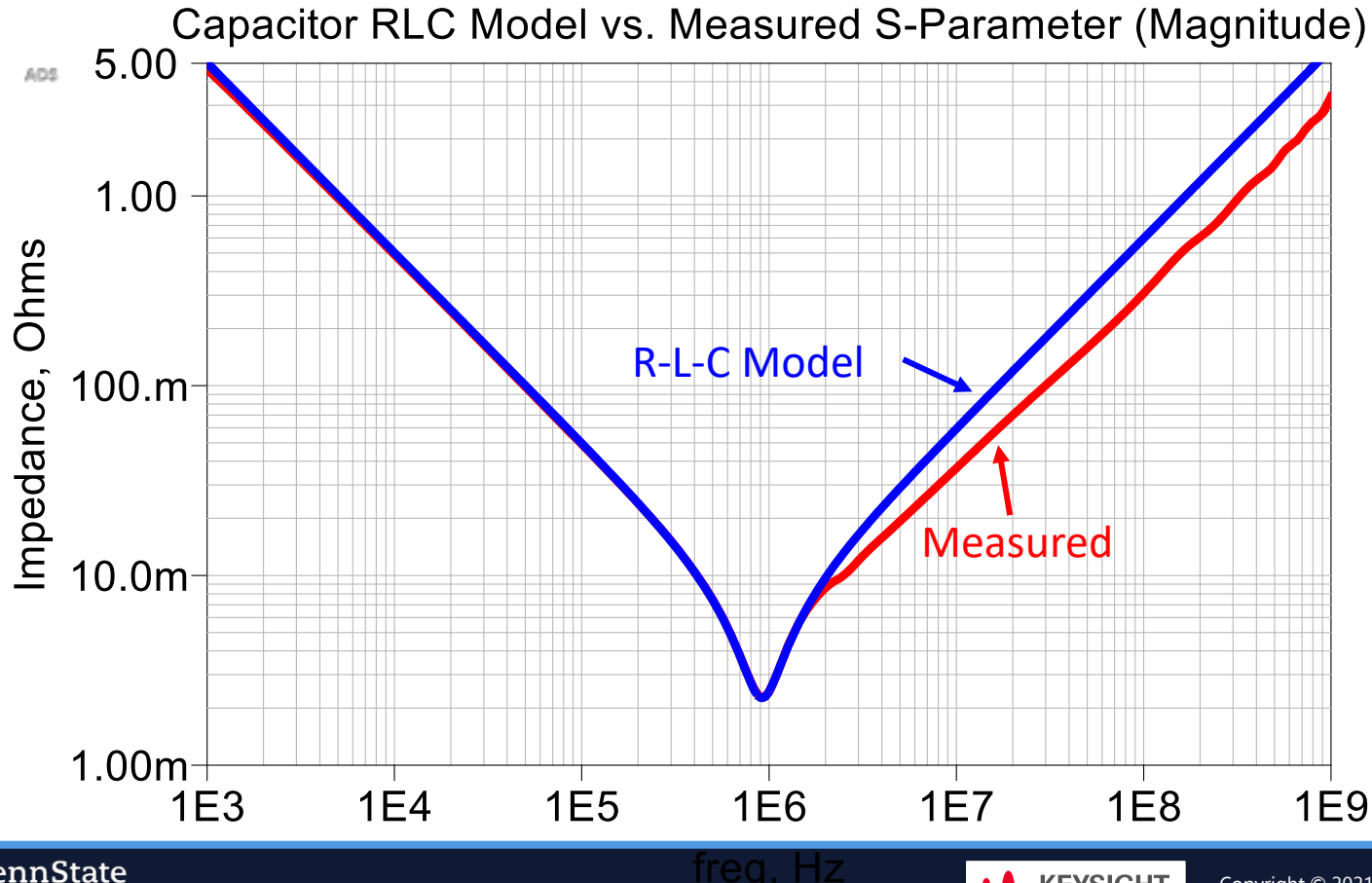
Ground Vias and PCB Stack-up Reduce Inductance



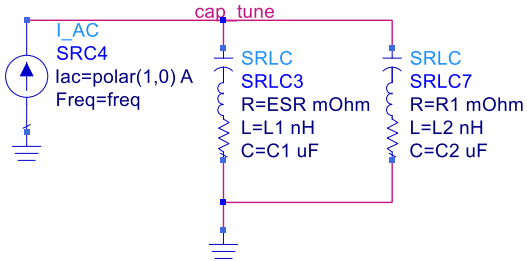
How to Measure the Capacitor.....



Series R-L-C Model Doesn't Match the Measurement



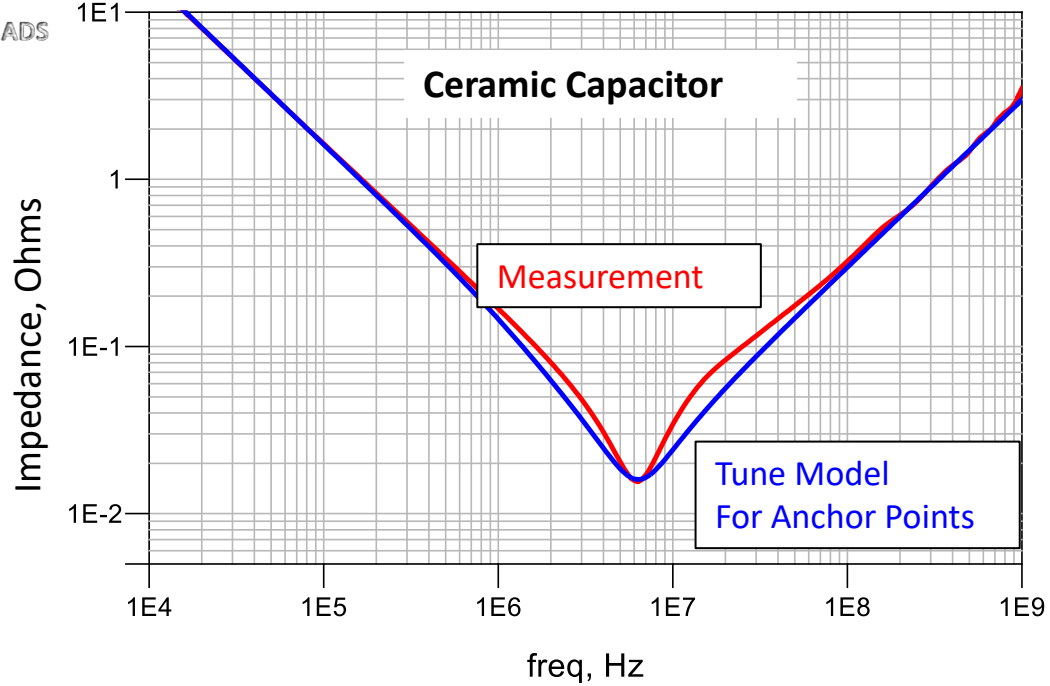
Ceramic Capacitors Can be Modeled as Parallel Caps



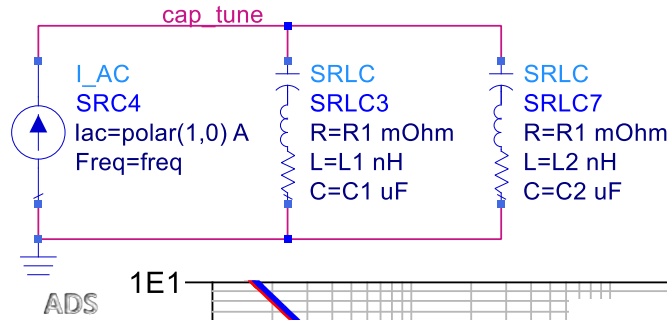
Anchor values

Var Eqn VAR
 VAR1
 $L_tot=0.475 \{t\}$
 $C_tot=0.984 \{t\}$
 $Fr=6300000 \{t\}$
 $ESR=16.01 \{t\}$

	L_tot	C_tot	Fr	ESR
Value	0.475	0.984	6300000	16.01
Max	0.75	1.8	7000000	20
Min	0.25	0.6	5000000	1
Step	0.05	0.12	1000	0.2
Scale	Lin	Lin	Lin	Lin



After Tuning



Shaping values

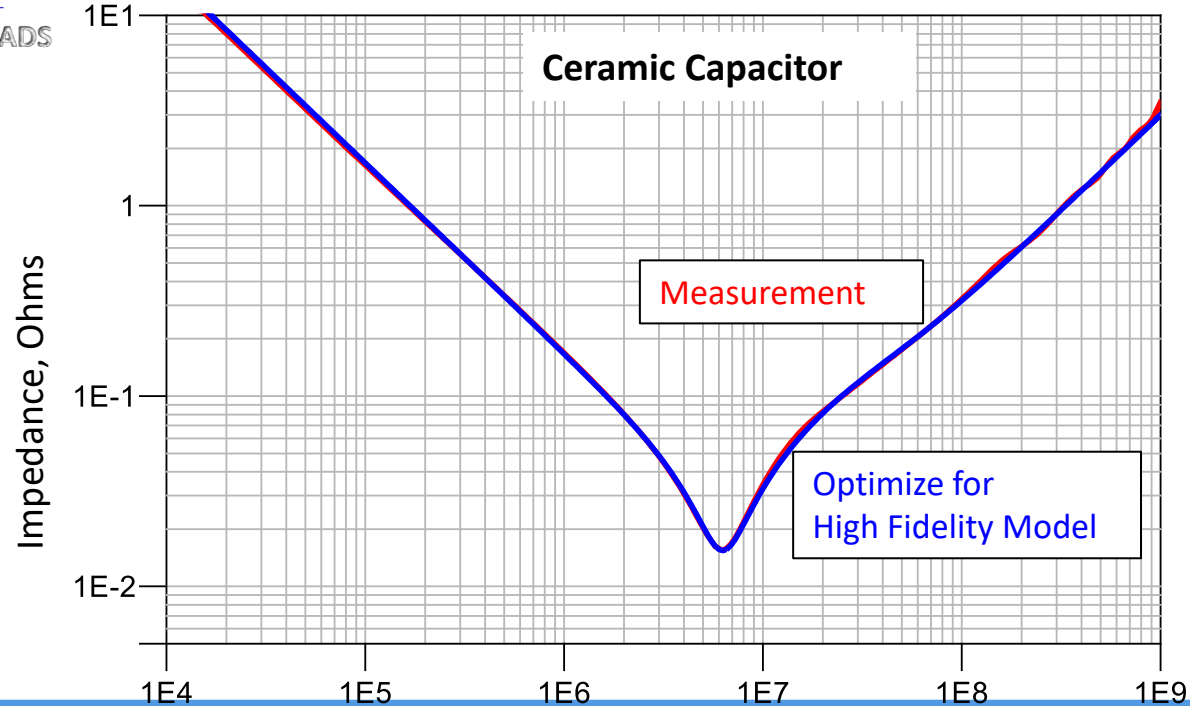
Var Eqn VAR
VAR3
C1=0.75 {t}
R1=311 {t}

Tune Parameters

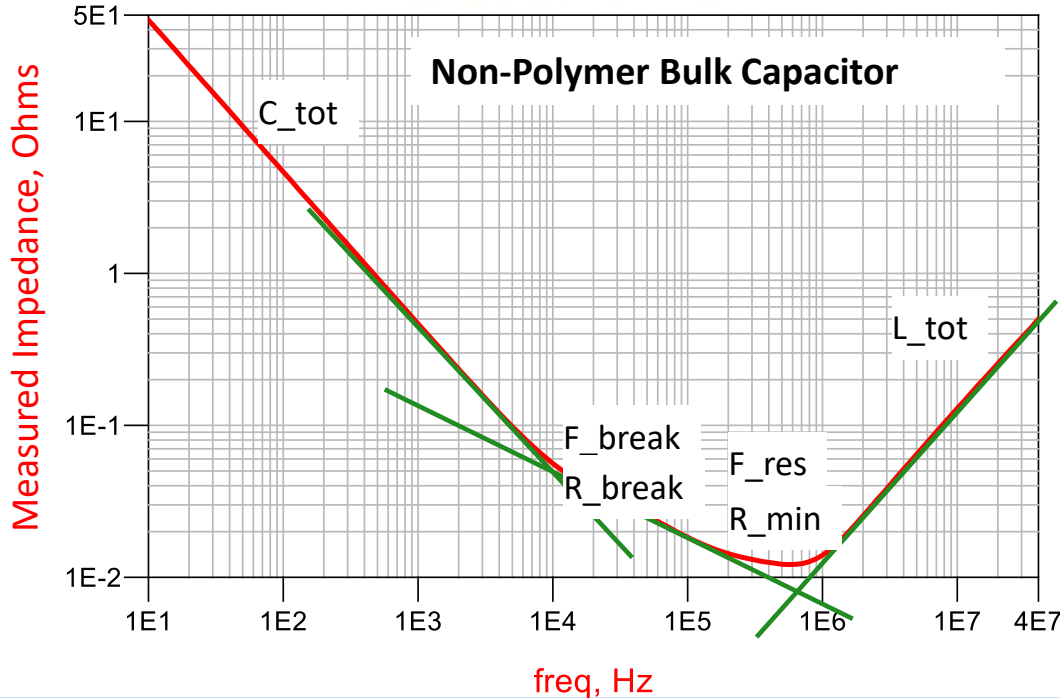
Simulate
While Slider Moves
Tune

Parameters
Include Opt Params
Enable/Disable...
 Display Full Name
 Snap Slider to Step
Traces and Values
Store... Recall...
Trace Visibility...
Reset Values
Close Unassociated Data Displays
Update Schematic
Close Help

C1	R1
0.814	435.4
1.5	466.5
.1	.1
0.1	31.1
Lin	Lin



Tantalum Capacitors Require a Different Model



Default values and tuning

```

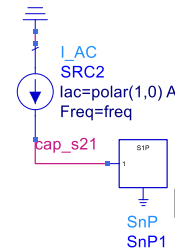
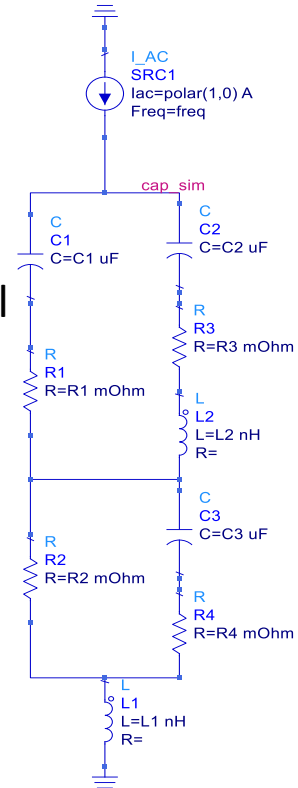
Var Eqn VAR
VAR6
C1=K1*1E9/(8.89*F_break*R_break)
R2=K2*R_res
L2=K3*5E15/(39.5*F_res*F_res*C_tot)
C3=K4*1E9/(15*F_res*R2)
R4=K5*R_res
R3=K6*R_res
    
```

Anchor values

```

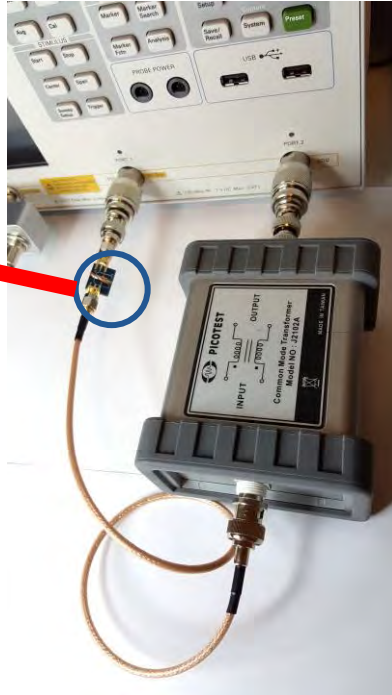
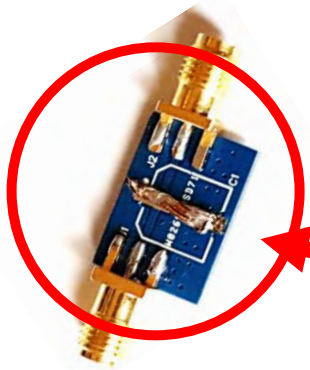
Var Eqn VAR
VAR9
L_tot=1.76 {t}
C_tot=330 {t}
F_break=11520 {t}
R_break=42 {t}
F_res=600000 {t}
R_res=12 {t}
    
```

Model

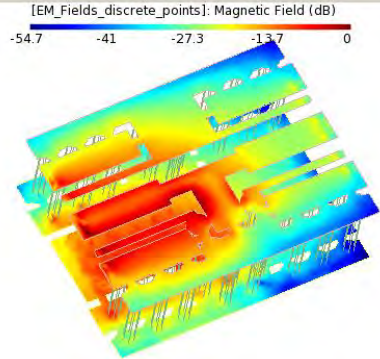
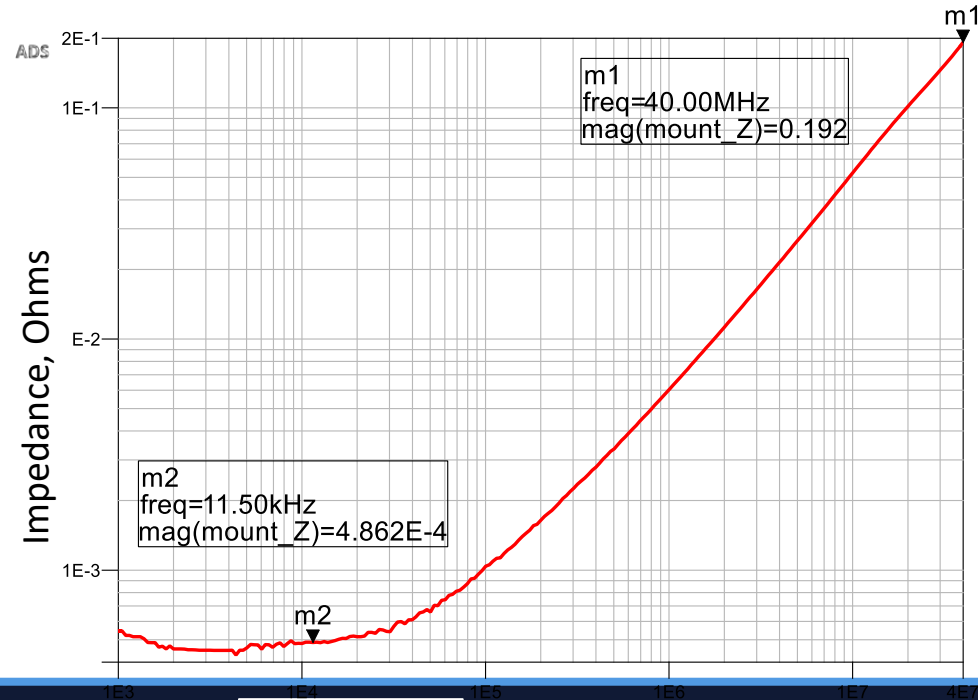


Measurement

Mounting Inductance Can be Added as R-L to Ground



$$L_{mount} = \frac{0.192}{2\pi \cdot 40MHz} = 764pH$$



An Optimizer Avoids Tedious Hand Tuning and Guessing

Meas Eqn

MeasEqn

cap_err

cap_err=mag(cap_meas)-mag(cap_sim)

cap_meas=cap_s21*25/(1-cap_s21)

GOAL

Goal
OptimGoal1
Expr="cap_err"
SimInstanceName="AC1"
Weight=1
LimitName[1]="limit1"
LimitType[1]="EqualTo"
LimitMin[1]=0
LimitMax[1]=0



OPTIM

Optim
Optim1
OptimType=Random
MaxIters=1000
UseAllOptVars=yes
UseAllGoals=yes
GoalName[1]=
SaveAllTrials=no

Before OPT

Shaping values

Var Eqn

VAR

VAR12

K1=1 {t} {o}

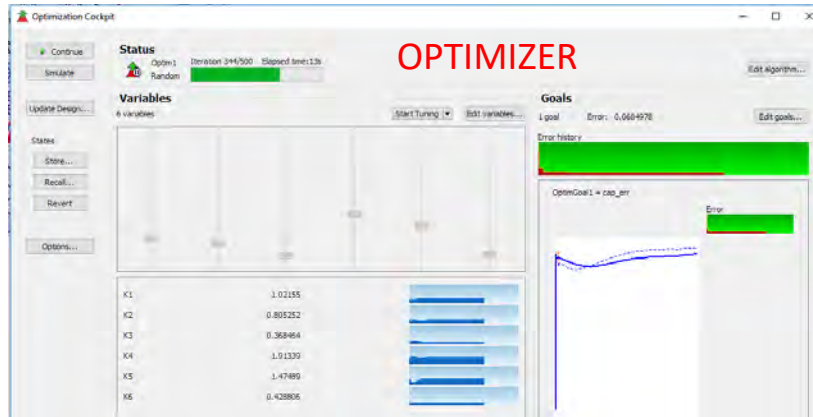
K2=1 {t} {o}

K3=1 {t} {o}

K4=1 {t} {o}

K5=1 {t} {o}

K6=1 {t} {o}



After OPT

Shaping values

Var Eqn

VAR

VAR11

K1=1.00876 {t} {o}

K2=0.837194 {t} {o}

K3=0.41982 {t} {o}

K4=2.09546 {t} {o}

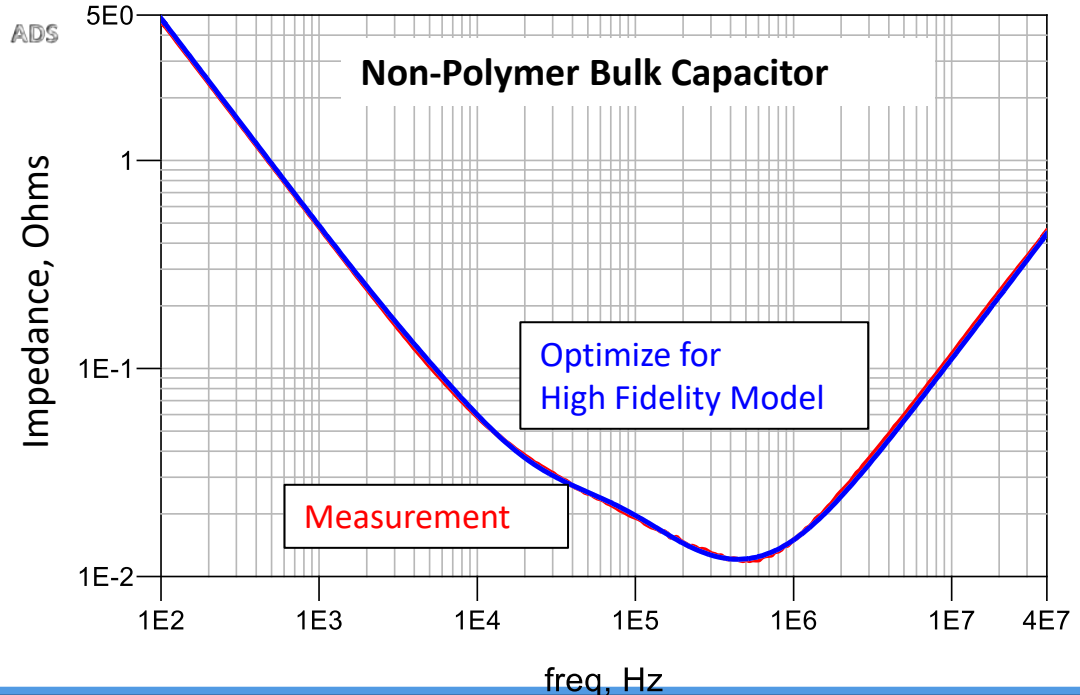
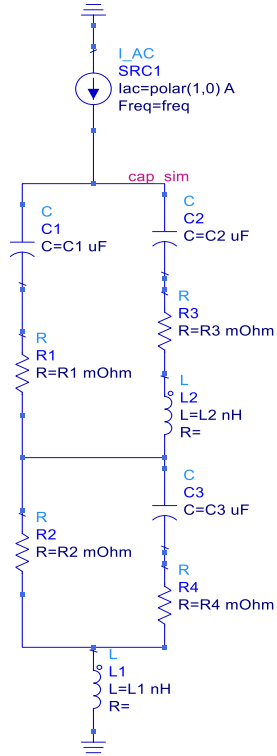
K5=1.56776 {t} {o}

K6=0.409425 {t} {o}

After Optimization

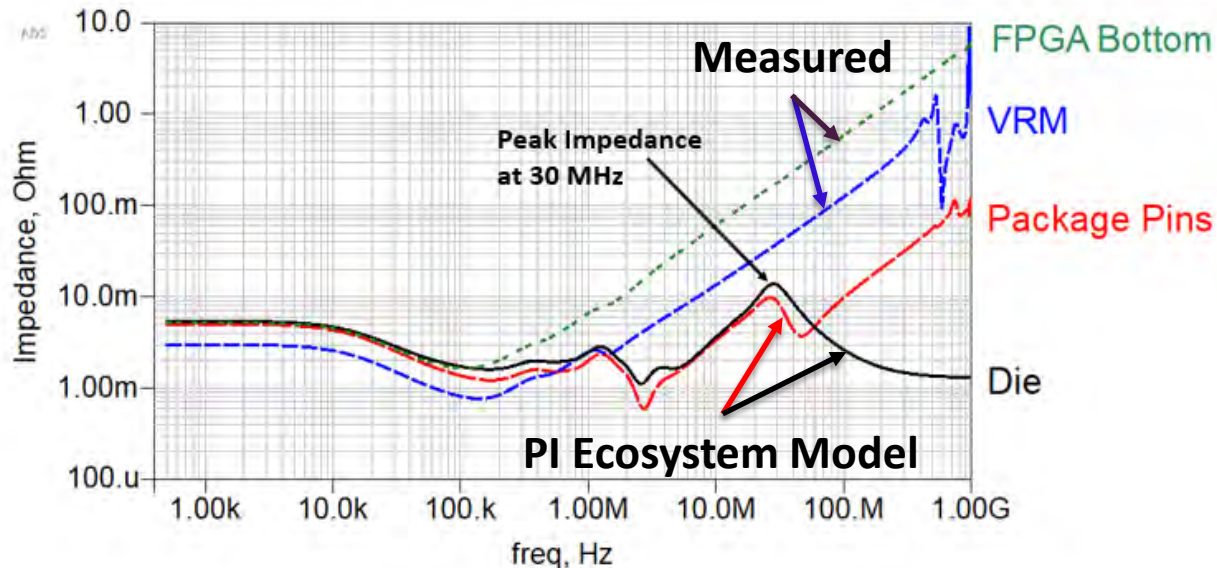
OPTIMIZER DETERMINED COMPONENT VALUES

C1_val	C2_val	C3_val	L1_val	L2_val	R1_val	R2_val	R3_val	R4_val
234.522	95.478	23.176	1.760	0.447	30.000	10.046	4.913	18.813



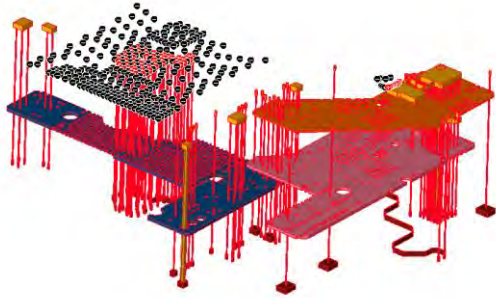
FPGA Package/Die, PCB PDN EM, and Capacitor Models are Critical

Impedance measurements did not see the resonance at 30 MHz!



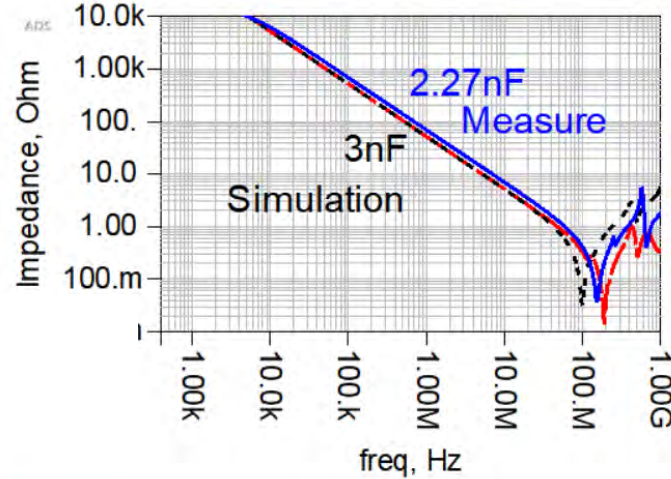
- Decoupling capacitors dominate the impedance of the VCCINT PDN.
- Measurements with VCCINT are only accessible on the bottom side of the FPGA and include the via inductance.
- PIPro PDN EM model with package/die (CPM) in ADS schematic accurately predicts impedance peak that measurement could not see.

PCB PDN Model



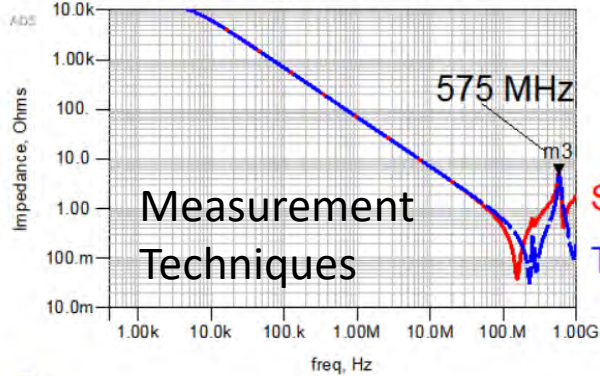
Simulation vs. Measurement

VCCINT @FPGA Bare PCB



Measure_Via_Bottom
 PIPro FPGA Via Bottom
 PIPro at VRM C1269

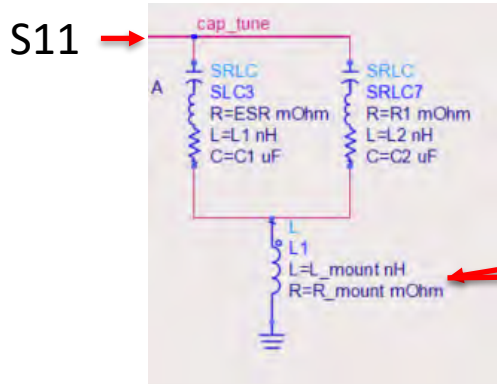
VCCINT @FPGA Bare PCB



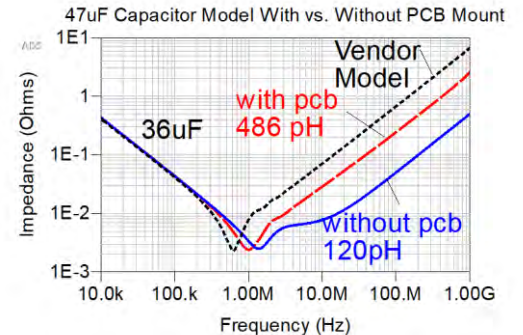
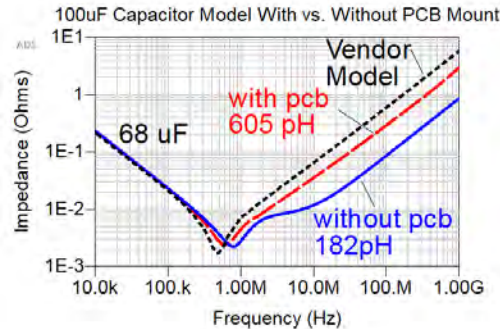
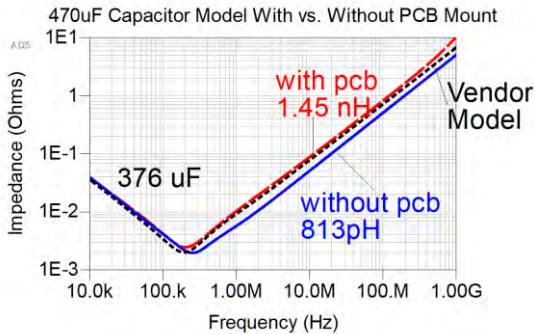
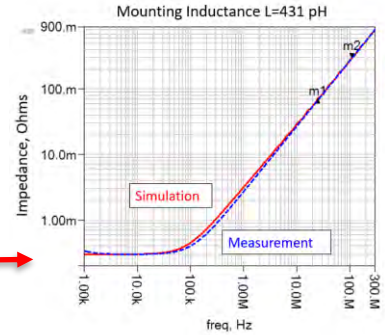
Same Side Probing
 Two Sided Probing

9

Capacitor Models without Mounting Inductance

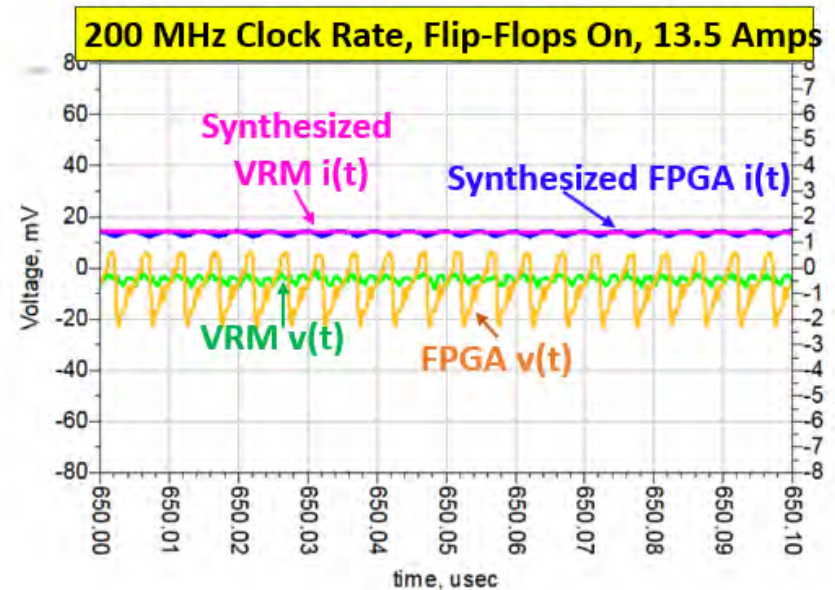
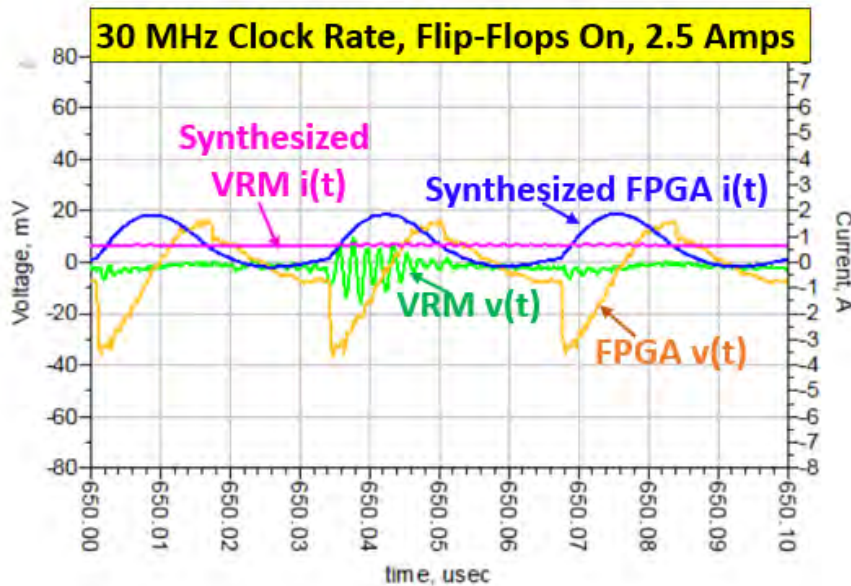


PCB EM Model includes this...
remove from capacitor model.



Measured Data Confirms the Simulated Results

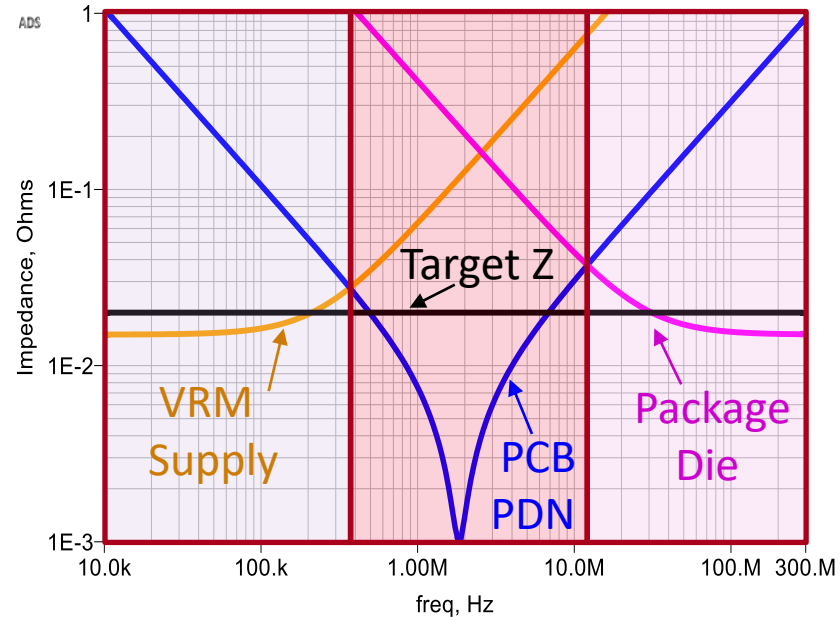
Power Integrity is not intuitive! Simulation with measurement enables predictive models for design optimization and troubleshooting 😊



Summary

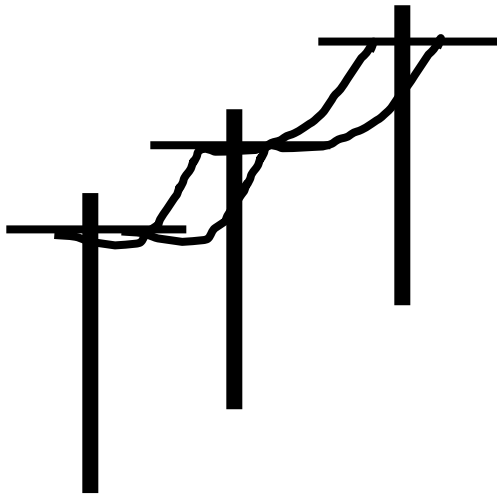
- Flat impedance is the PI design goal!
- Learn how to make 2-port shunt impedance measurements to get good models, verify simulations, and debug noise problems.
- Beware of vendor capacitor models....avoid double counting the mounting inductance when used with EM models of the PCB.

Individual Source Impedance
VRM, PCB PDN, and Package+Die



History Lesson – The Transatlantic Cable

Engineered design vs. Costly Debug/redesign



What is so hard about stringing a wire between the transmitter and the receiver?

Where was the SI Engineer in 1858?

Transatlantic telegraph cable

In 1858...signal quality declined rapidly, slowing transmission to an almost unusable speed. The cable was destroyed the following month when Wildman Whitehouse applied excessive voltage to it while trying to achieve faster operation.

Questions For Your Next Design

PI Engineers require simulation and measurement tools

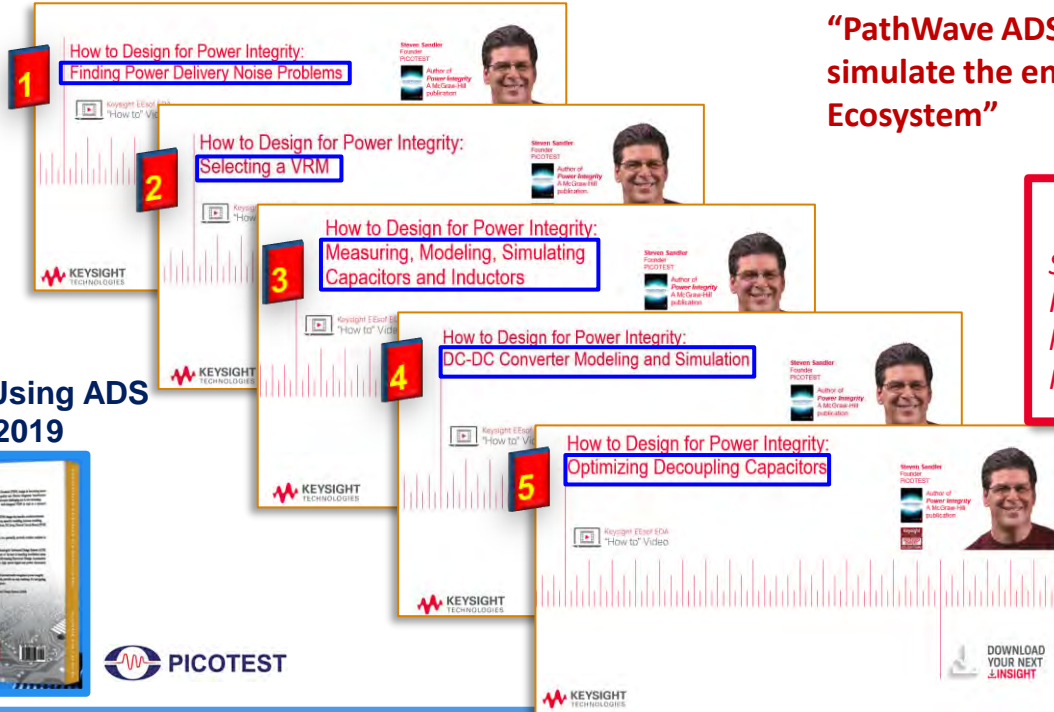
1. Are your designs still leveraging decade capacitor values?
2. Are poor designs band-aided with added filters and more capacitors?
3. Where is the PI engineer?

PathWave ADS Simulates the Power Integrity Ecosystem

How to Design for Power Integrity 5 Part Series on YouTube



Steve Sandler, Founder of Picotest
Over 40 years of experience in Power Electronics



“PathWave ADS is the only tool that can simulate the end to end Power Integrity Ecosystem”

KEY TAKE AWAY

Steve Sandler is an expert at Power Integrity Ecosystem simulations, and he does it all in PathWave ADS with PIPro!

Power Integrity Using ADS Published 2019



Resources:

- H. Barnes, J. Carrel, S. Sandler, “A Method for Dynamic Load Current Testing with a Benchtop Power Supply” DesignCon 2020.
- Keysight sponsored “How to Design for Power Integrity” YouTube video series with Steve Sandler of Picotest: <http://www.keysight.com/find/how-to-videos-for-pi>
- Keysight PathWave ADS for Power Integrity: <https://www.keysight.com/us/en/products/software/pathwave-design-software/pathwave-advanced-design-system/pathwave-ads-high-speed-digital-design.html>
- Picotest Power Integrity Measurement Test Accessories: www.Picotest.com
- Xilinx ZCU104 Evaluation Kit: <https://www.xilinx.com/products/boards-and-kits/zcu104.html>

Acknowledgements-

Co-collaborators Steve Sandler of Picotest and Jack Carrel of Xilinx

Thank you!

QUESTIONS?